

RL78 Family

Data Flash Library Type 04
Japanese Release

Installer name: RENESAS_RL78_FDL_T04_xVxx

16-Bit Single-Chip Microcontrollers

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General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

HOW TO USE THIS MANUAL

Readers

This manual is intended for user engineers who wish to understand the functions of the RL78 microcontrollers Data Flash Library Type 04 and design and develop application systems and programs for these devices.

Refer to the following list for the target MCUs.

"Self-Programming Library (Japanese Release) and Supported MCUs" (R20UT2861XJxxxx)
"RL78 Family Self RAM list of Flash Self Programming Library" (R20UT2944)

Purpose

This manual is intended to give users an understanding of the methods (described in the **Organization** below) for using the Data Flash Library Type 04 to rewrite the data flash memories.

Organization

The RL78 Data Flash Library Type 04 user's manual is separated into the following parts:

- Overview
- Programming Environment
- Data Flash Library Function

How to Read This Manual

It is assumed that the readers of this manual have general knowledge of electrical engineering, logic circuits, and microcontrollers.

- To gain a general understanding of functions:
→ Read this manual in the order of the **CONTENTS**.
- To know details of the RL78 Microcontroller instructions:
→ Refer to **CHAPTER 3 DATA FLASH LIBRARY FUNCTION**.

The mark <R> shows major revised points.

Conventions

Data significance:	Higher digits on the left and lower digits on the right
Active low representations:	$\overline{\text{xxx}}$ (overscore over pin and signal name)
Note:	Footnote for item marked with Note in the text
Caution:	Information requiring particular attention
Remark:	Supplementary information
Numerical representations:	Binary ...xxxx or xxxxB
	Decimal ...xxxx
	Hexadecimal ...xxxxH or '0x'xxxx

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CHAPTER 1 OVERVIEW

1. 1 Overview

The data flash library is a software library to perform operations to the data flash memory with the firmware installed on the RL78 microcontroller.

The data flash library performs rewriting and reading of the data flash memory when called from the user program.

Use this data flash library user's manual with the user's manual of the target RL78 microcontroller.

Terms The meanings of the terms used in this manual are described below.

- Data flash library

Library for data flash memory operations with the functions provided by the RL78 microcontroller.

It cannot perform operation to the code flash memory.

- Flash self-programming library

Library for code flash memory operation with the functions provided by the RL78 microcontroller.

Operation to the data flash memory cannot be done.

- EEPROM emulation library

Library that provides functions to store data to the built-in flash memory like an EEPROM.

- Block number

Number that shows a block of the flash memory. It is the unit of erasure operation in the Data Flash Library Type 04.

- Internal verification

To check if the signal level of the flash memory cell is appropriate after writing to the flash memory. If an error occurs in internal verification, the device is determined as failed. However, if data erasure, data writing, and internal verification are performed and completed normally after the internal verification error, the device is determined as normal.

- FDL

Abbreviation of "Data Flash Library."

- Sequencer

The RL78 microcontroller has a dedicated circuit for controlling the flash memory. In this document, this circuit is called the "sequencer."

- BGO (background operation)

State in which rewriting of the flash memory can be done while operating the user program by letting the sequencer to control the flash memory. For the overview and details, refer to "2.1 Hardware Environment" and "3.4 BGO (background operation)."

- Status check

When the sequencer is used, the processing to check the state of the sequencer (state of control for the flash memory) with the program controlling the flash memory is required. In this document, the processing to check the state of the sequencer is called "status checking."

1.2 Calling the Data Flash Library Type 04

To perform rewriting of the data flash memory with the Data Flash Library Type 04, the initialization processing for the Data Flash Library Type 04 and the functions corresponding to the functions used need to be executed from the user program by using the C language or assembly language.

Figure 1-1 shows the state transition diagram of the Data Flash Library Type 04. Figure 1-2 shows an example of the code flash memory rewriting flow by using the Data Flash Library Type 04.

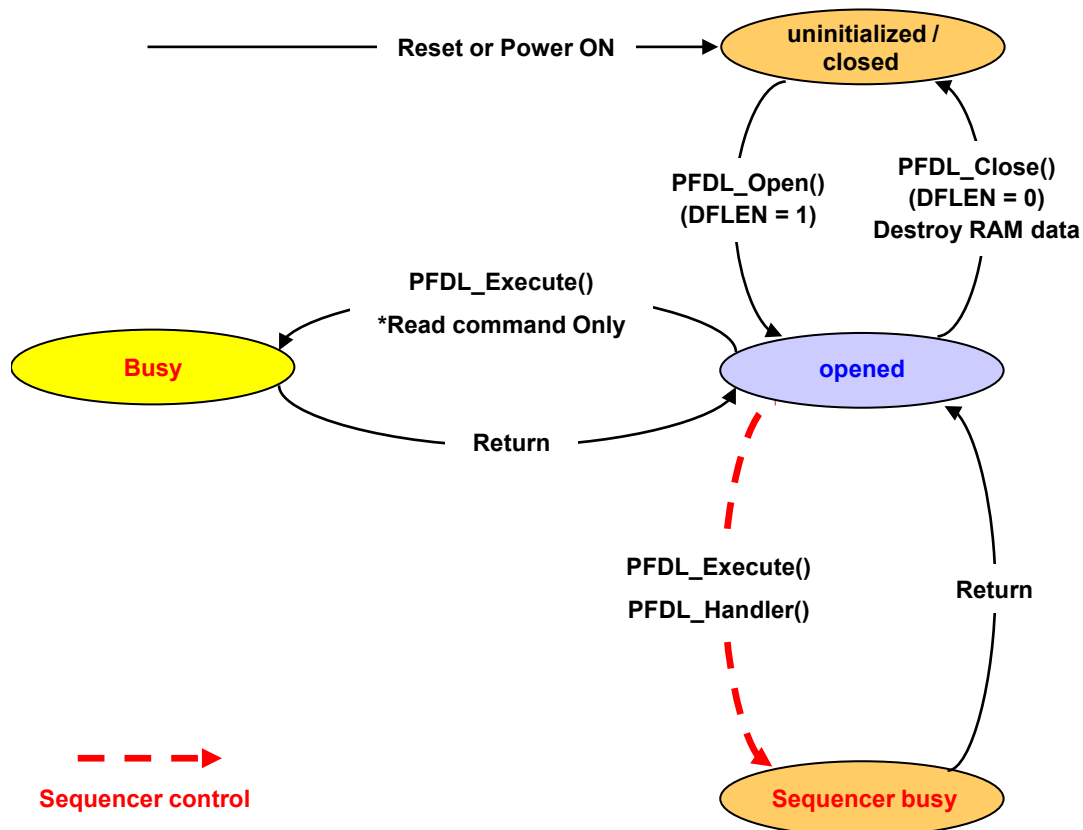


Figure 1-1. State Transition Diagram of the Data Flash Library Type 04

[Overview of the state transition diagram]

To operate the data flash memory by using the Data Flash Library Type 04, the provided functions need to be executed sequentially to perform processing. For details of functions, refer to section 3, Data Flash Library Function.

(1) uninitialized/closed

State at Power ON and Reset. To execute the flash self-programming library, EEPROM emulation library, data flash library other than Type 04, STOP command, or HALT command, execute PFDL_Close from the opened state to cause a transition to this state.

(2) opened

State in which the PFDL_Open() function has been executed from the uninitialized / closed state and the data flash library can be executed. In the period from the execution of PFDL_Close to the transition to the uninitialized / closed state, the flash self-programming library, EEPROM emulation library, data flash library other than Type 04, STOP command, or HALT command cannot be executed.

When the PFDL_Open function is executed, the data flash control register (DFLCTL) is set to the state where accessing the data flash memory is permitted (DFLEN = 1), and when the PFDL_Close function is executed, the DFLCTL is set to the access inhibit state (DFLEN = 0).

(3) busy

State in which the specified processing is being executed. The control does not return to the user program until the processing is completed.

(4) sequencer busy

State in which the specified processing is being executed with the sequencer. The PFDL_Execute function specifies the details of control to the data flash memory, and the PFDL_Handler function performs a status check. The executed function returns to the user program without waiting for the completion of sequencer operation. The code flash memory cannot be referred to while the sequencer is being used.

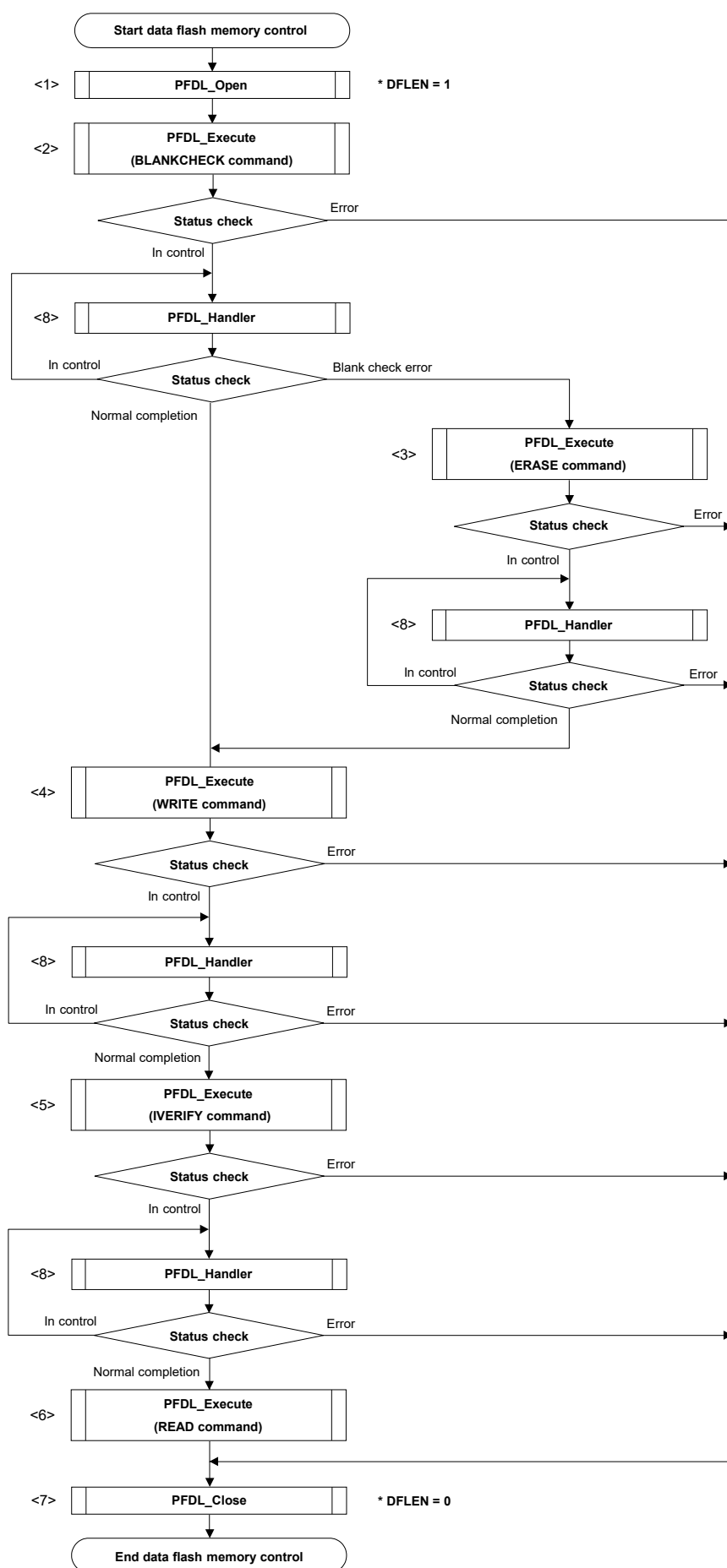


Figure 1-2. Example of Flow of the Data Flash Library Type 04 Operation

Data Flash Library Type 04

<1> PFDL_Open: Initializing and starting the RAM used for the Data Flash Library Type 04

The PFDL_Open function is called to initialize the RAM used for the Data Flash Library Type 04 to enable the Data Flash Library Type 04.

Set the data flash control register (DFLCTL) to the state where accessing the data flash memory is permitted (DFLEN = 1).

<2> PFDL_Execute: Blank checking 1 to 1024 bytes for the specified address

The PFDL_Execute function (with the PFDL_CMD_BLANKCHECK_BYTES command specified) is called to perform blank checking of 1 to 1024 bytes for the specified address (confirm that the area is writable).

The processing cannot be executed across blocks.

<3> PFDL_Execute: Erasing the specified block (1-KB)

The PFDL_Execute function (with the PFDL_CMD_ERASE_BLOCK command specified) is called to erase the specified block (1-KB).

<4> PFDL_Execute: Writing 1 to 1024 bytes data to the specified address

The PFDL_Execute function (with the PFDL_CMD_WRITE_BYTES command specified) is called to write 1 to 1024 bytes to the specified address. The processing cannot be executed across blocks. Writing can be performed only to an area in the blank state or an area that has been erased. It is impossible to rewrite (overwrite) an area that has been written (including areas to which 0xFF has been written).

<5> PFDL_Execute: Internal verification of 1 to 1024 bytes for the specified address

The PFDL_Execute function (with the PFDL_CMD_IVERIFY_BYTES command specified) is called to perform internal verification of 1 to 1024 bytes for the specified address. The processing cannot be executed across blocks.

Note: Internal verification checks if the signal level of the flash memory cell is appropriate. Checking by comparing data is not performed.

<6> PFDL_Execute: Reading 1 to 1024 bytes for the specified address

The PFDL_Execute function (with the PFDL_CMD_READ_BYTES command specified) is called to read 1 to 1024 bytes for the specified address. All the processing of reading is executed within the PFDL_Execute function. The processing cannot be executed across blocks.

<7> PFDL_Close: Ending the Data Flash Library Type 04

The PFDL_Close function is called to end the Data Flash Library Type 04. Also set the data flash control register (DFLCTL) to the state where accessing the data flash memory is inhibited (DFLEN = 0). The PFDL_Close function is executed to end control of the data flash memory.

<8> PFDL_Handler: Status checking

The PFDL_Handler function is called to perform status checking. Status checking must be performed until the control to the data flash memory by the sequencer is finished.

CHAPTER 2 PROGRAMMING ENVIRONMENT

This chapter describes the hardware environment and software environment required to rewrite the data flash memory using the Data Flash Library Type 04.

2.1 Hardware Environment

The Data Flash Library Type 04 for the RL78 microcontroller uses the sequencer to execute rewrite control of the data flash memory. Because the sequencer controls the data flash memory, the user program can be operated during data flash memory control. This is called BGO (background operation).

During rewriting of the data flash memory, the data flash memory cannot be referred to. However, the code flash memory can be referred to, so interrupt processing, user program, and the Data Flash Library Type 04 can be allocated in the ROM for operation as usual. ^{Note}

Figure 2-1 shows the state during a rewrite of the data flash memory. Figure 2-2 shows an example of execution of the flash library functions to perform rewriting of the data flash memory.

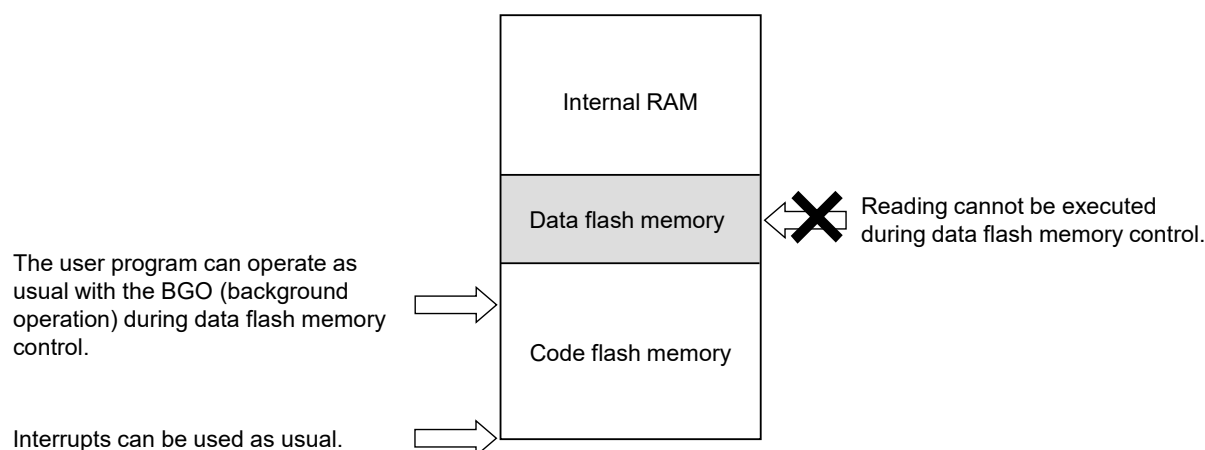


Figure 2-1. State during Rewrite of Data Flash Memory

Note: Interrupts are prohibited for the R5F10266 product while using the Data Flash Library Type 04.

- After an execution request of the desired processing is made to the sequencer of the RL78 microcontroller, the control is immediately returned to the user program. For the result of the control of the data flash memory, the status check function (PFDL_Handler function) must be called from the user program to check the control state of the data flash memory.

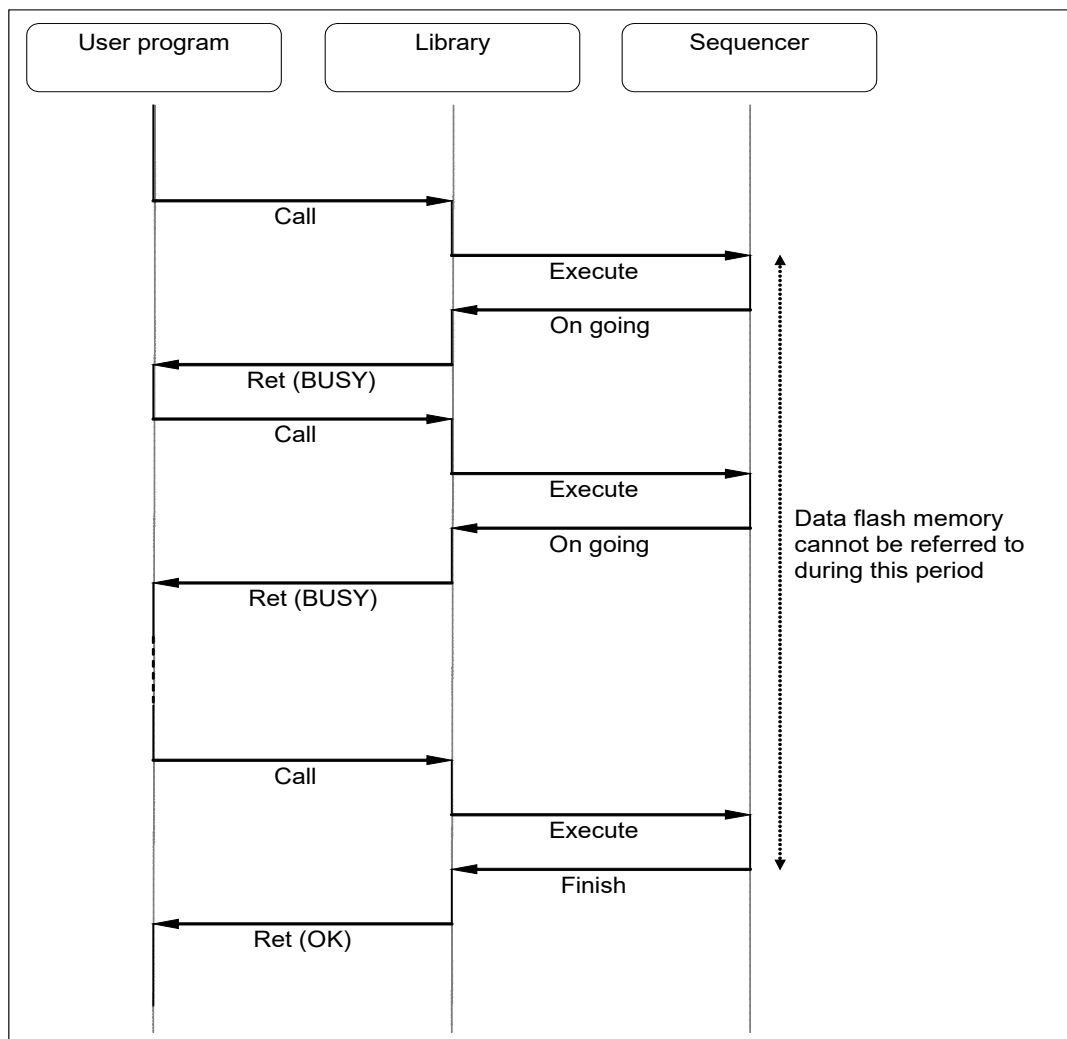


Figure 2-2. Example of Rewrite Control of Data Flash Memory

2. 1. 1 Initialization

When rewriting the data flash memory by using the Data Flash Library Type 04, make the following settings.

(1) Starting high-speed on-chip oscillator

During use of the Data Flash Library Type 04, keep the high-speed on-chip oscillator running. When the oscillator is stopped, start it before using the Data Flash Library Type 04.

(2) Setting CPU operating frequency^{Note1}

In order to calculate the timing in the Data Flash Library Type 04, set the CPU operating frequency at initialization. For the method for setting the frequency, see the description of the PFDL_Open() function.

(3) Setting flash memory programming mode^{Note2}

In order to set the flash memory programming mode for writing, either of the flash memory programming modes shown below should be specified when initializing the Data Flash Library Type 04. See the description of the PFDL_Open function for the settings of the flash memory programming modes.

- Full speed mode
- Wide voltage mode

- Notes 1. The CPU operating frequency is used as a parameter for the calculation of internal timing used in the Data Flash Library Type 04. This setting does not affect the CPU operating frequency. This is not the operating frequency for the high-speed on-chip oscillator.
2. For details of the flash memory programming mode, see the target RL78 microcontroller user's manual.

2. 1. 2 Data flash control register (DFLCTL)

The data flash control register (DFLCTL) enables or disables access to the data flash memory. When the PFDL_Open function is executed, the data flash control register (DFLCTL) is set to the state where access to the data flash memory is enabled (DFLEN = 1), and when the PFDL_Close function is executed, the DFLCTL is set to the access disabled state (DFLEN = 0).

Address : F0090H Initial value : 00H R/W

Abbreviation	7	6	5	4	3	2	1	0
DFLCTL	0	0	0	0	0	0	0	DFLEN

DFLEN	Controlling access to the data flash memory
0	Access to the data flash memory is disabled
1	Access to the data flash memory is enabled

Figure 2-3. Format of Data Flash Control Register (DFLCTL)

Note: Refer to the user's manual of the target RL78 microcontroller for more information on the settings of the data flash control register (DFLCTL).

2. 1. 3 Blocks

The flash memory of the RL78 microcontroller is divided into 1 Kbyte blocks. In the data flash library, erasure processing is performed for the data flash memory in the units of the blocks.

For reading, writing, blank checking, or internal verification, specify the start address^{Note} and execution size for execution.

Figure 2-4 shows an example of block positions and block numbers of the data flash memory.

Note The address value used when reading and writing data in the flash memory. is a relative address that starts from block 0 of the data flash memory (block 0 is assumed as address 0). Note that this is not an absolute address.

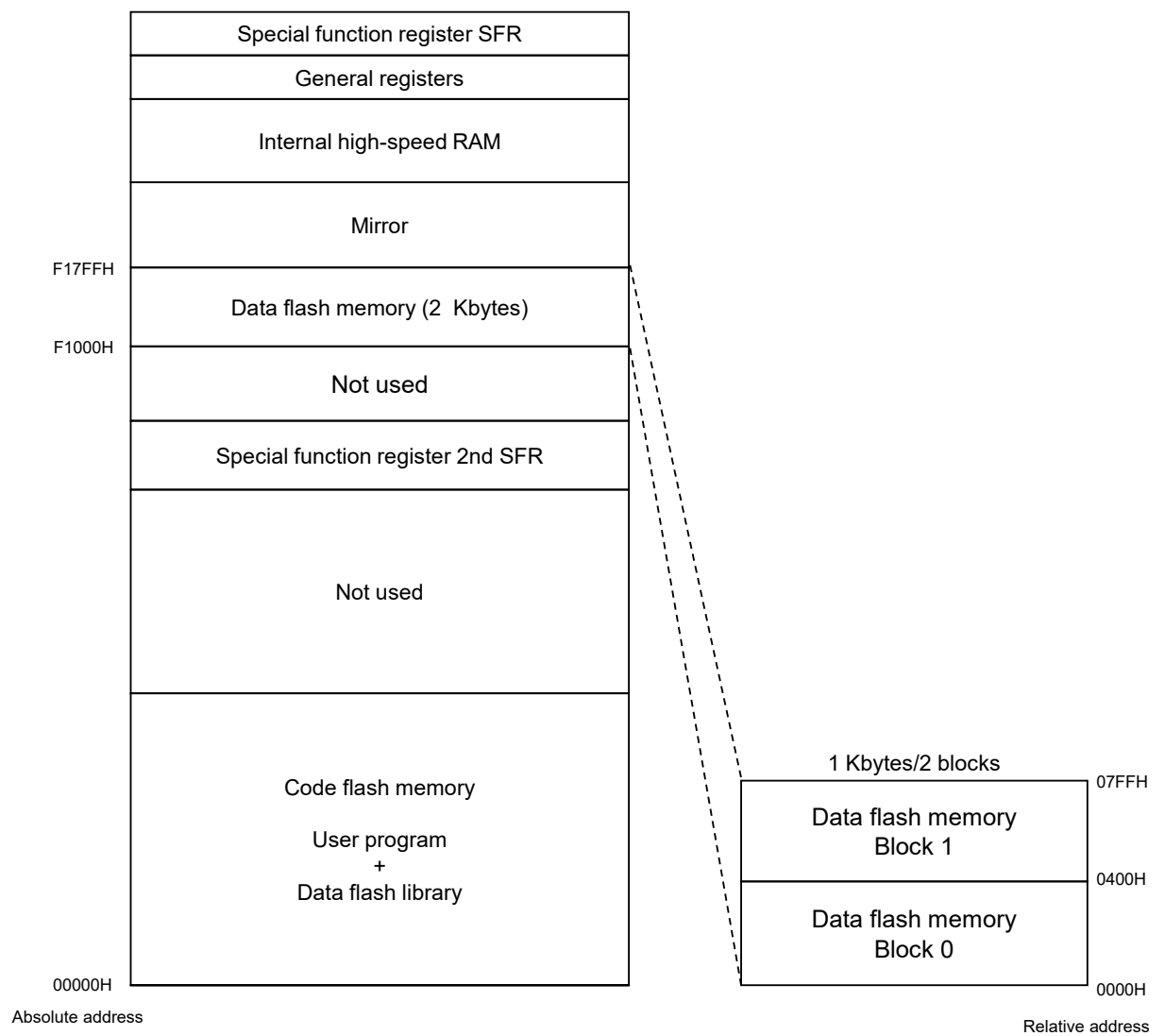


Figure 2-4. Blocks of Data Flash Memory (RL78/G12: When Data Flash Memory is 2 Kbytes)

2. 1. 4 Processing time of the Data Flash Library Type 04

This section describes the time required to process the Data Flash Library Type 04 functions (except for the Read command).

The number of clock cycles required to execute flash functions differs depending on whether the flash functions are allocated to the internal ROM area (flash memory) or they are allocated to the internal RAM area. When the functions are executed in the RAM, the processing time may increase to a maximum of double the time needed when they are executed in the ROM.

This section shows the processing time when the data flash library functions are executed in the ROM. For each segment of data flash library functions, see **3.2 Segments of Data Flash Library Functions**.

(1) Data Flash Library Type 04 function processing time

The flash function processing time is the time required from when a user-created program calls a flash function until the processing ends and control returns to the user-created program.

Figure 2-5 shows an overview of the flash function processing time, and Tables 2-1 and 2-2 show the processing time.

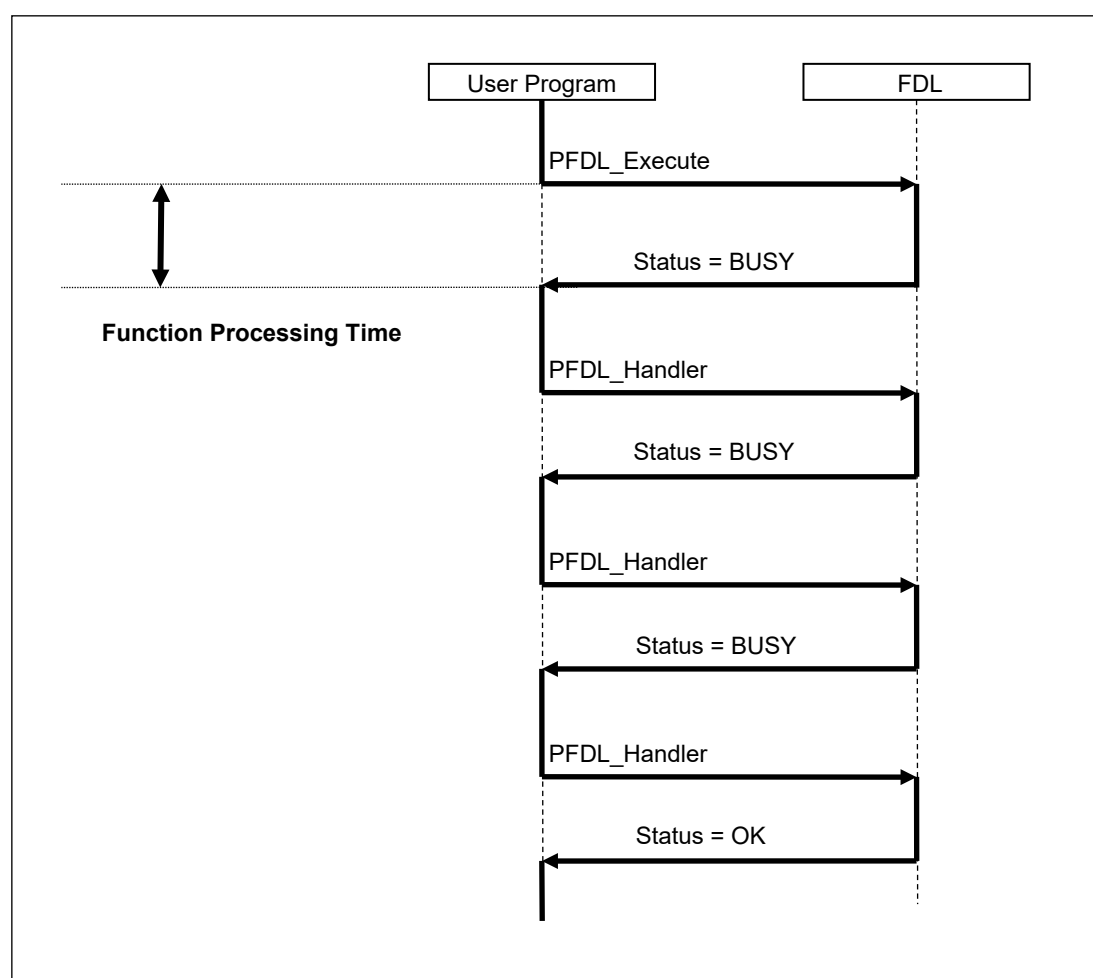


Figure 2-5. Overview of the Data Flash Library Type 04 Function Processing Time

Table 2-1. Function Processing Time in Full Speed Mode

PFDL_Functions	Max. (μs)
PFDL_Open	862 / fCLK
PFDL_Execute(Erase)	536 / fCLK
PFDL_Execute(BlankCheck)	484 / fCLK
PFDL_Execute(Write)	549 / fCLK
PFDL_Execute(IVerify)	502 / fCLK
PFDL_Execute(Read)	53 / fCLK + 17 / fCLK × Bytes
PFDL_Handler	251 / fCLK + 14
PFDL_Close	823 / fCLK + 443
PFDL_GetVersionString	10 / fCLK

- Remarks 1. fCLK: CPU operating frequency (For example, when using a 20 MHz clock, fCLK is 20.)
2. Bytes: The number of bytes to be written (For example, when specifying 8 bytes, Bytes is 8.)

Table 2-2. Function Processing Time in Wide Voltage Mode

PFDL_Functions	Max. (μs)
PFDL_Open	862 / fCLK
PFDL_Execute(Erase)	536 / fCLK
PFDL_Execute(BlankCheck)	484 / fCLK
PFDL_Execute(Write)	549 / fCLK
PFDL_Execute(IVerify)	502 / fCLK
PFDL_Execute(Read)	53 / fCLK + 17 / fCLK × Bytes
PFDL_Handler	251 / fCLK + 14
PFDL_Close	779 / fCLK + 968
PFDL_GetVersionString	10 / fCLK

- Remarks 1. fCLK: CPU operating frequency (For example, when using a 20 MHz clock, fCLK is 20.)
2. Bytes: The number of bytes to be written (For example, when specifying 8 bytes, Bytes is 8.)

(2) Recommended interval of PFDL_Handler (status check)

The PFDL_Handler function is used to check the status except for the reading processing. However, the end of each process cannot be confirmed if the PFDL_Handler function is executed before control by the sequencer finishes. Therefore, spacing each process executed by each flash function by a specific time is useful to enhance the efficiency of status checking.

In addition, because a write process using the Write command must be triggered by status check processing every byte, the status must be checked each time 1-byte is written.

Figures 2-6 and 2-7 show overviews of recommended interval, and Tables 2-3 and 2-4 show the interval time.

When writing 3 bytes using the Data Flash Library Type 04, the sequencer writes data in a 1-byte unit. Therefore, when 1-byte is written, the PFDL_Handler function must trigger the next write. If the PFDL_Handler function is not executed while there are still bytes to be written, the next write does not start, and thus the write process does not end.

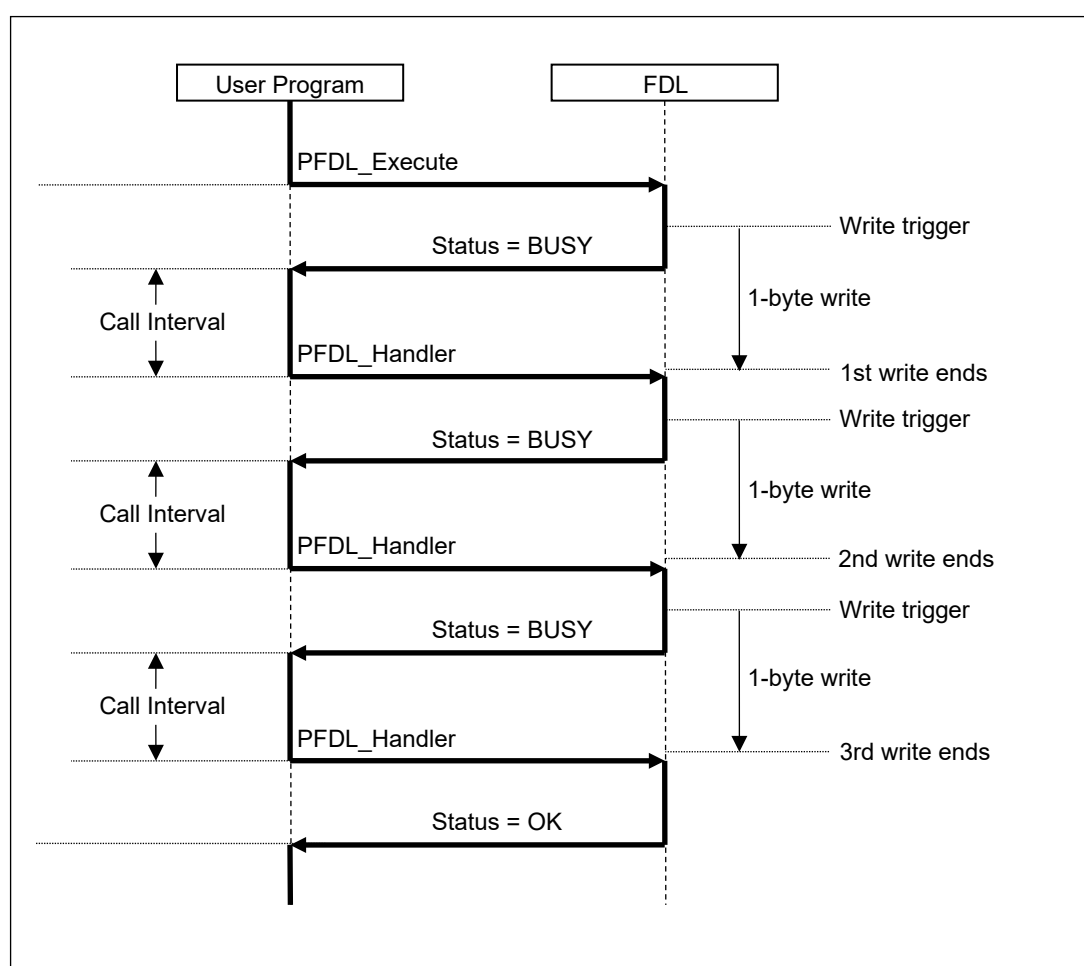


Figure 2-6. Overview of Interval for Checking Status When Using Write Command (When Writing 3 Bytes)

When a process is executed by a command other than Write, the sequencer is in the busy state until all processes end. A trigger by the PFDL_Handler function is therefore not required.

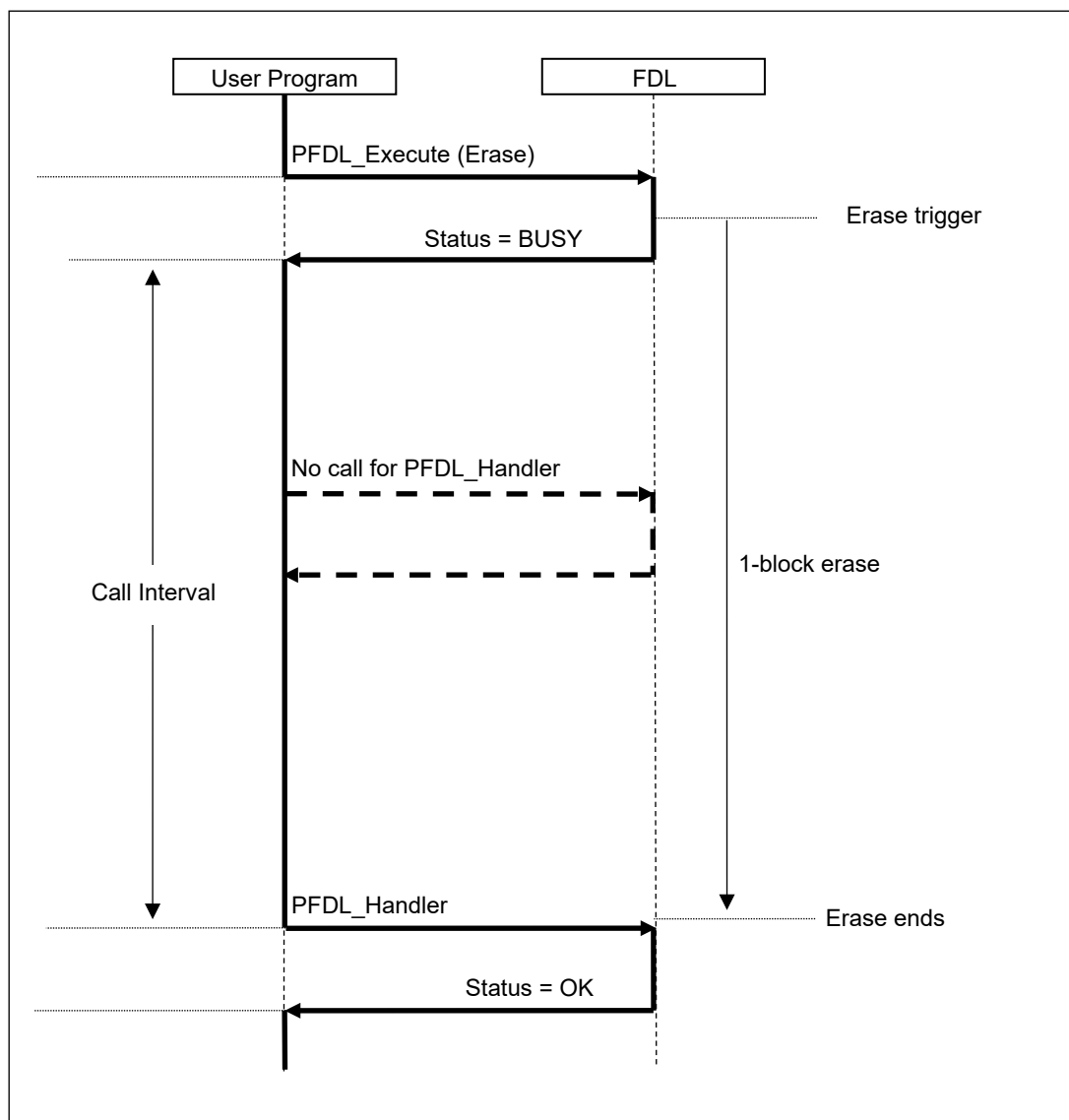


Figure 2-7. Overview of Interval for Checking Status When Using a Command Other Than Write
(When Erasing Flash Memory)

Table 2-3. Recommended Interval of PFDL_Handler (Status Check) in Full Speed Mode

PFDL_Functions	Max. (μs)
PFDL_Execute(Erase)	When block is blank $5860 / f_{CLK} + 335$
	When block is not blank $12734 / f_{CLK} + 6946$
PFDL_Execute(BlankCheck)	$33 / f_{CLK} + 18 + (6 / f_{CLK} + 0.31) \times \text{Bytes}$
PFDL_Execute(Write)	$61 / f_{CLK} + 47$
PFDL_Execute(IVerify)	$13 / f_{CLK} + 17 + (28 / f_{CLK} + 4) \times \text{Bytes}$

Remarks 1. fCLK: CPU operating frequency (For example, when using a 20 MHz clock, fCLK is 20.)
2. Bytes: The number of bytes to be written (For example, when specifying 8 bytes, Bytes is 8.)

Table 2-4. Recommended Interval of PFDL_Handler (Status Check) in Wide Voltage Mode

PFDL_Functions	Max. (μs)
PFDL_Execute(Erase)	When block is blank $5065 / f_{CLK} + 1167$
	When block is not blank $11144 / f_{CLK} + 8620$
PFDL_Execute(BlankCheck)	$30 / f_{CLK} + 57 + (5 / f_{CLK} + 1.084) \times \text{Bytes}$
PFDL_Execute(Write)	$57 / f_{CLK} + 99$
PFDL_Execute(IVerify)	$14 / f_{CLK} + 44 + (17 / f_{CLK} + 29) \times \text{Bytes}$

Remarks 1. fCLK: CPU clock frequency (For example, when using a 20 MHz clock, fCLK is 20.)
2. Bytes: The number of bytes to be written (For example, when specifying 8 bytes, Bytes is 8.)

(3) Total processing time

The total processing time when each command is executed in the PFDL_Execute function is the time until successful termination. This does not include the overhead time (call interval) before the user executes the PFDL_Handler function or the time until abnormal termination due to errors.

Figure 2-8 shows an overview of total processing time when each command is executed in the PFDL_Execute function, and Tables 2-5 and 2-6 show the total processing time.

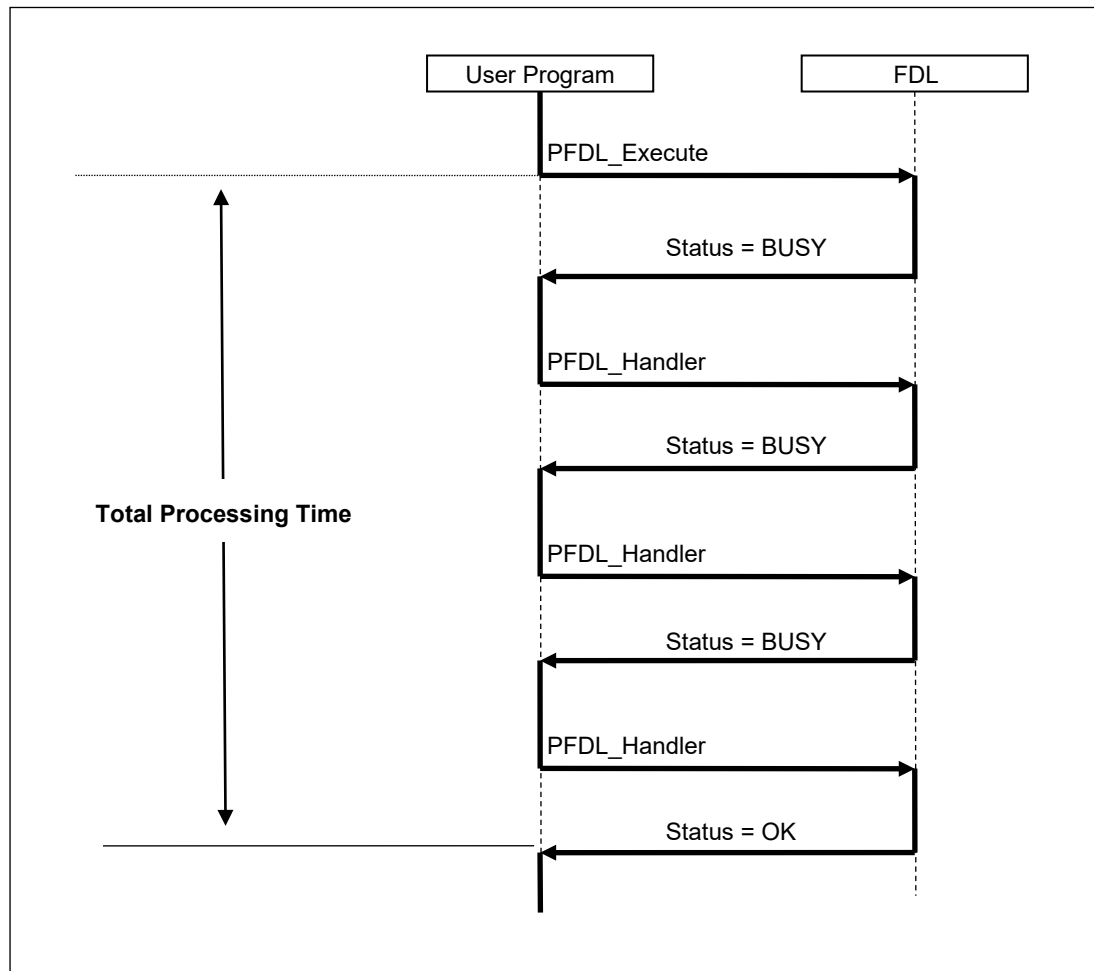


Figure 2-8. Overview of Total Processing Time

Table 2-5. Total Processing Time of the Data Flash Library Type 04 in Full Speed Mode

PFDL_Functions	Typical (μs)	Max. (μs)
PFDL_Execute(Erase)	11250 / fCLK + 5800	281561 / fCLK + 264790
PFDL_Execute(BlankCheck)	906 / fCLK + 30 + (5 / fCLK + 0.26) × Bytes	1088 / fCLK + 36 + (6 / fCLK + 0.31) × Bytes
PFDL_Execute(Write)	487 / fCLK + 11.67 + (212 / fCLK + 39.17) × Bytes	585 / fCLK + 14 + (714 / fCLK + 430) × Bytes
PFDL_Execute(IVerify)	621 / fCLK + 25 + (23 / fCLK + 3.33) × Bytes	746 / fCLK + 30 + (28 / fCLK + 4) × Bytes

Remarks 1. fCLK: CPU operating frequency (For example, when using a 20 MHz clock, fCLK is 20.)

2. Bytes: The number of bytes to be written (For example, when specifying 8 bytes, Bytes is 8.)

Table 2-6. Total Processing Time of the Data Flash Library Type 04 in Full Speed Mode

PFDL_Functions	Typical (μs)	Max. (μs)
PFDL_Execute(Erase)	9925 / fCLK + 7194.17	249000 / fCLK + 299307
PFDL_Execute(BlankCheck)	903 / fCLK + 62.5 + (4 / fCLK + 0.9) × Bytes	1084 / fCLK + 75 + (5 / fCLK + 1.084) × Bytes
PFDL_Execute(Write)	487 / fCLK + 11.67 + (208 / fCLK + 82.5) × Bytes	585 / fCLK + 14 + (669 / fCLK + 954) × Bytes
PFDL_Execute(IVerify)	622 / fCLK + 48.33 + (14 / fCLK + 24.17) × Bytes	747 / fCLK + 58 + (17 / fCLK + 29) × Bytes

Remarks 1. fCLK: CPU operating frequency (For example, when using a 20 MHz clock, fCLK is 20.)

2. Bytes: The number of bytes to be written (For example, when specifying 8 bytes, Bytes is 8.)

2.2 Software Environment

Because the Data Flash Library Type 04 for the RL78 Family program needs to be allocated to the user area, the size of the program code will be consumed in the user program area.

To run the data flash library, the CPU, stack, and data buffer are used.

<R> The Data Flash Library Type 04 is provided for the CA78K0R, CC-RL and LLVM compilers. In the tables in the remainder of this document, the versions of the Data Flash Library Type 04 for the CA78K0R, CC-RL and LLVM compilers are respectively abbreviated as CA78, CCRL and LLVM.

Table 2-7 lists the software resources required^{Note1, 2}, and Figures 2-9 and 2-10 show examples of arrangement in RAM.

<R> **Table 2-7. Software Resources Used by the Data Flash Library Type 04**

Item	Size(byte)		Restrictions on Allocation and Usage ^{Note1,2}
	CA78	CCRL LLVM	
Self-RAM ^{Note3}	0 to 136 ^{Note3}	0 to 136 ^{Note3}	The self-RAM area used by RL78 Family Data Flash Library Type 04 Ver. 1.05 differs depending on the device. For details, refer to "RL78 Family Self RAM list of the Flash Self Programming Library(R20UT2944)".
Stack	46 max. ^{Note4}	40 max. ^{Note4}	Can be allocated to a RAM area other than the self-RAM and the area from FFE20H to FFEFFH ^{Note2} .
Data Buffer ^{Note5}	1 to 1024	1 to 1024	
Function arguments	0 to 8	0 to 8	
Library size	ROM: 177 max	ROM: 168 max	Can be allocated to a program area other than the self-RAM and the area from FFE20H to FFEFFH.

Notes: 1. For devices not shown in the RL78 Family Self RAM list of Flash Self Programming Library(R20UT2944), contact your Renesas sales agency.

2. This table is not applicable to the R5F10266 product. Refer to **2.2.1 Software resources of the R5F10266 product**.

3. An area used as the working area by the Data Flash Library Type 04 is called self-RAM in this manual and the Release Note. The self-RAM requires no user setting because it is an area that is not mapped and automatically used at execution of the data flash library (previous data is discarded). When the data flash library is not used, the self-RAM can be used as a normal RAM space.

<R> 4. This is the sum of the amount of stack (maximum of 4 bytes) necessary for calling a function and the stack used by the library (42 bytes in the case of the version for the CA78K0R compiler. 36 bytes in the case of the version for the CC-RL compiler. 36 bytes in the case of the version for the LLVM compiler).

5. The data buffer is a RAM area necessary for inputting data for reading and writing. The necessary size changes according to the unit of reading and writing. When reading and writing of 1 byte is performed, the required data buffer size is 1 byte.

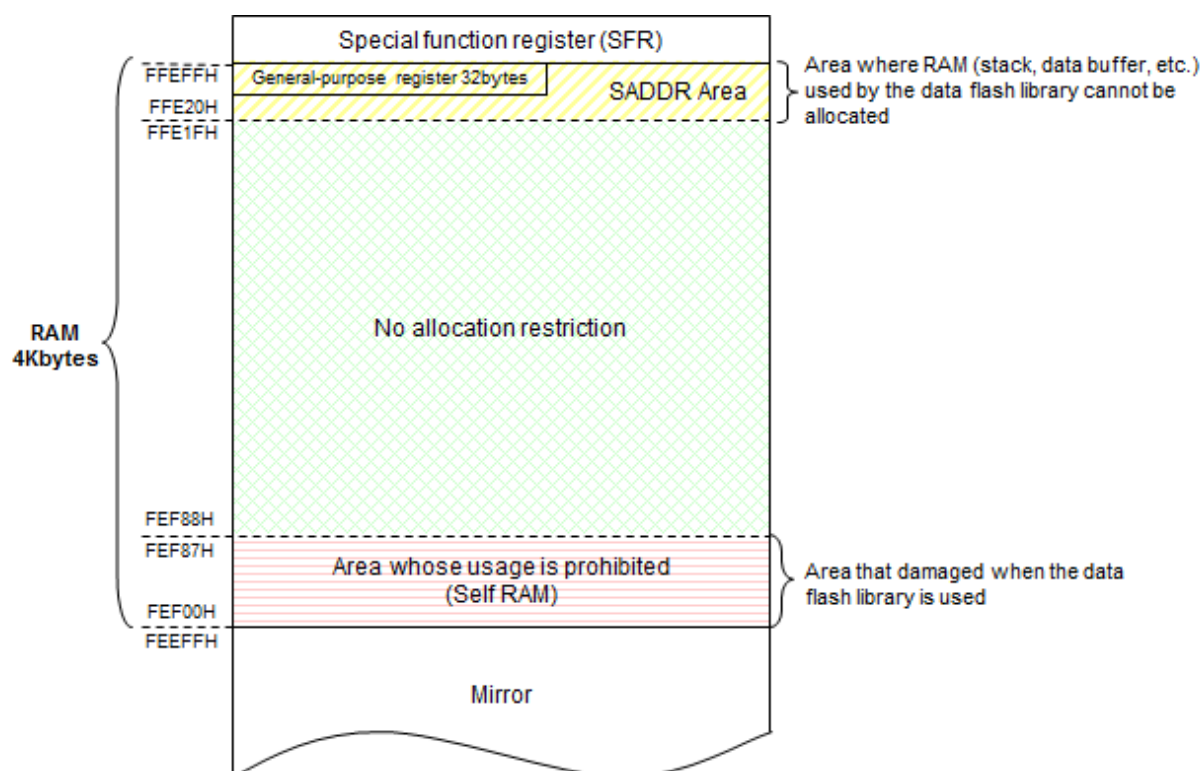


Figure 2-9. Example 1 of Arrangement in RAM Including Self-RAM
(RL78/G13: Product with 4Kbytes RAM and 64Kbytes ROM)

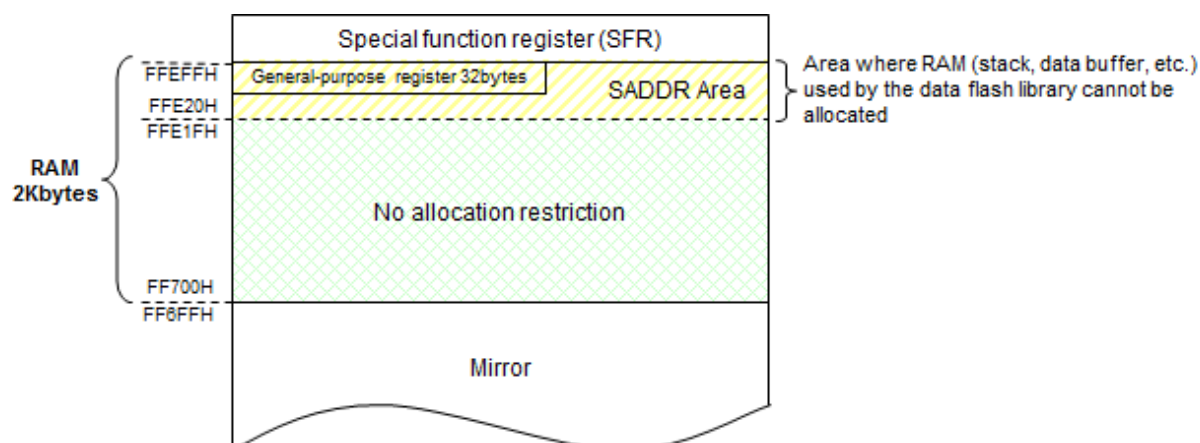


Figure 2-10. Example 2 of Arrangement in RAM without Self-RAM
(RL78/G13: Product with 2Kbytes RAM and 32Kbytes ROM)

2. 2. 1 Software resources of the R5F10266 product

The R5F10266 product has usage inhibited areas and restrictions on stack allocation. Therefore, the settings of software resources differ from other products. Using an interrupt is also prohibited.

Table 2-8 shows a list of software resources necessary for the R5F10266 product; figure 2-11, an example of RAM area; and figures 2-12 and 2-13, examples of a stack allocation for each language in use.

<R> **Table 2-8. The Data Flash Library Type 04 Software Resources of the R5F10266 Product**

Item	Size(byte)		Restrictions on Allocation and Usage ^{Note2, 3}
	CA78	CCRL LLVM	
Self-RAM ^{Note3}	0	0	There is no self-RAM.
Stack	46 max. ^{Note1}	40 max. ^{Note1}	Allocated in the RAM area of FFEA2H-FFEDFH ^{Note2} .
Data Buffer ^{Note3}	1 to 24	1 to 24	Can be allocated to a RAM area other than the area from FFE20H to FFEFFH.
Function arguments	8	8	
Library size	ROM: 177 max.	ROM: 168 max.	Allocate in the code flash memory area.

- <R> Notes: 1. This is the sum of the amount of stack (maximum of 4 bytes) necessary for calling a function and the stack used by the library (42 bytes in the case of the version for the CA78K0R compiler. 36 bytes in the case of the version for the CC-RL compiler. 36 bytes in the case of the version for the LLVM compiler).
2. Be sure to specify the stack for use by the library within this area.
3. The data buffer is a RAM area necessary for inputting data for reading and writing. The necessary size changes according to the unit of reading and writing. When reading and writing of 1 byte is performed, the required data buffer size is 1 byte.

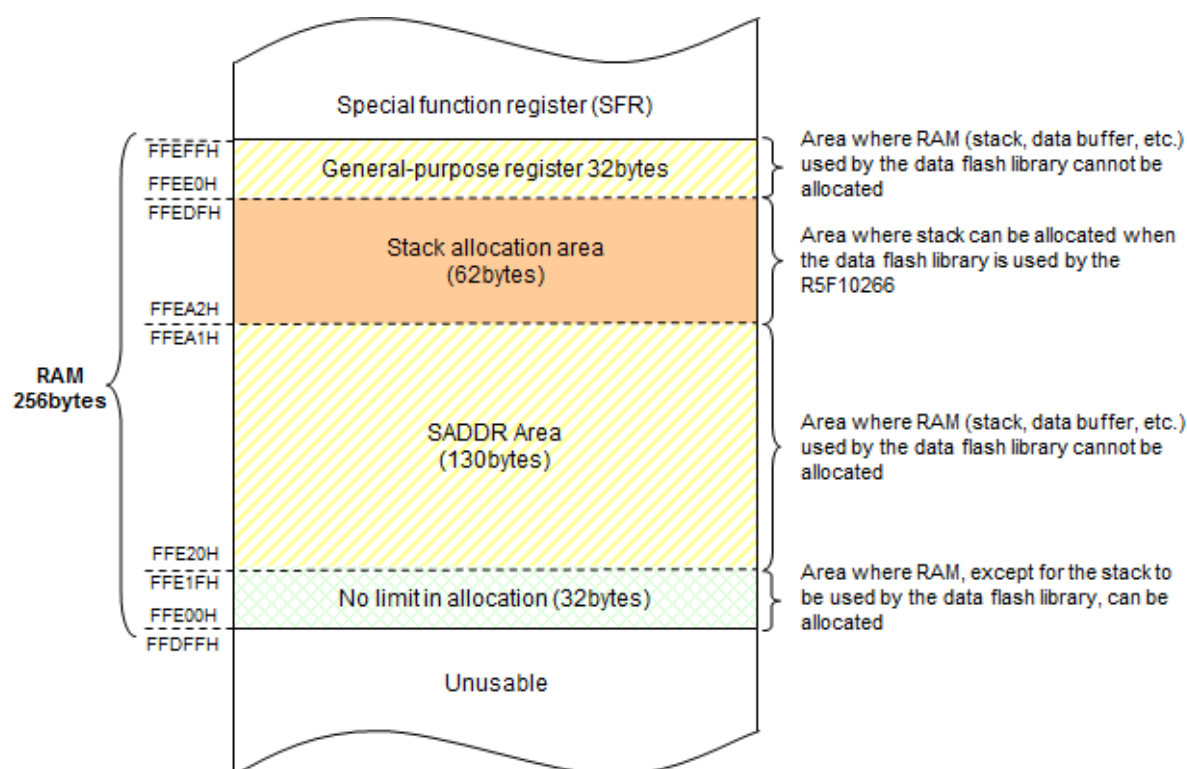


Figure 2-11. Example of RAM Area When Data Flash Library is Used in the R5F10266 Product

<R>

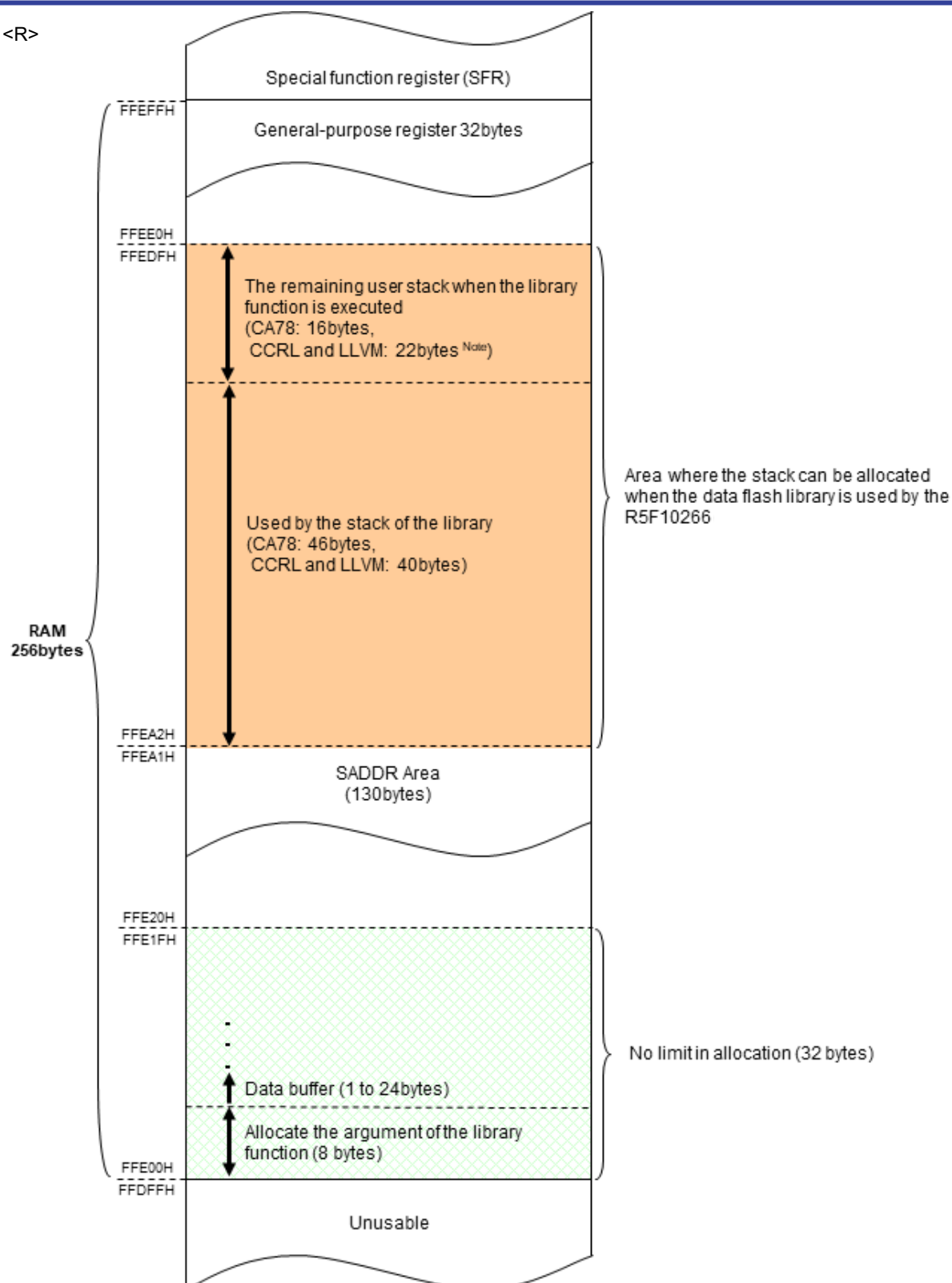


Figure 2-12. Example 1 of Stack Allocation
(for the R5F10266 product/ in the case of assembly language)

<R> Note: When the on-chip debugging function is used, the stack space to be used by the on-chip debugging function (4 bytes) is required, so this stack must be allocated in this area. When this stack is allocated, the remaining amounts of space that can be used as the user stack while the Data Flash Library Type 04 is in use are 12 bytes with the version for the CA78K0R compiler and 18 bytes with the version for the CC-RL compiler and the LLVM compiler.

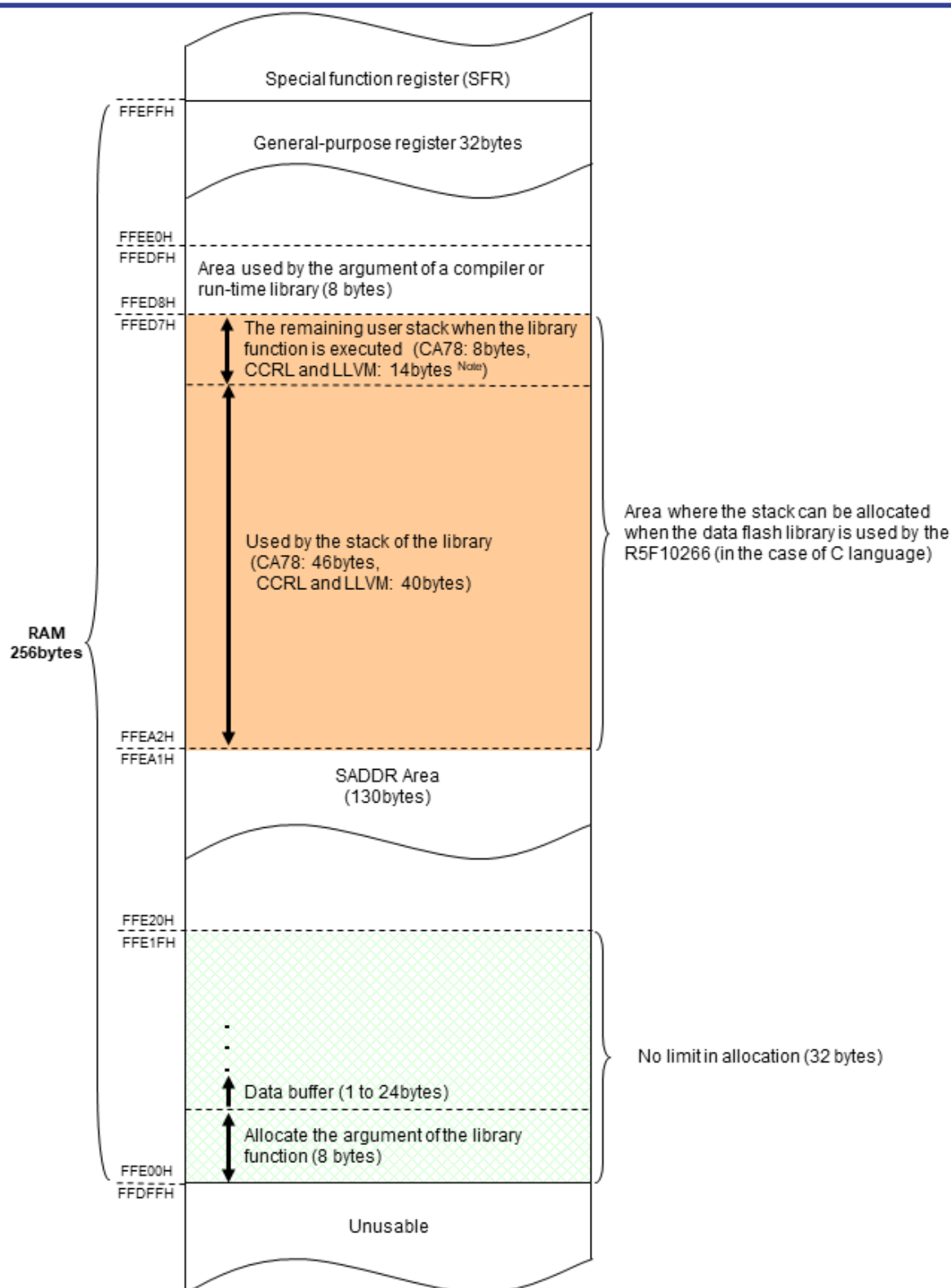


Figure 2-13. Example 2 of Stack Allocation
(for the R5F10266 product/ in the case of C language)

<R> Note: When using C language, the stack space (4 bytes) used when the main function is executed from the start-up routine is required. When the on-chip debugging function is used, the stack space (4 bytes) used by the on-chip debugging function is required. Thus, these stacks must be placed in this area. When both of these parts of the stack space are in use, the remaining amounts of space that can be used as the user stack while the Data Flash Library Type 04 is in use are 0 bytes with the version for the CA78K0R compiler and 6 bytes with the version for the CC-RL compiler and the LLVM compiler.

2. 2. 2 Self-RAM

The Data Flash Library Type 04 may use a RAM area as the working area. This area is called the "self-RAM". The data used in the self-RAM is defined within the library, so no user definition of data is required.

When a data flash library function is called, the data in the self-RAM area is rewritten.

The self-RAM area used for data flash programming varies depending on the microcontroller, and the user RAM may be used in some devices.

<R> In such a device, the user needs to allocate the self-RAM area to the user RAM; be sure to allocate the self-RAM area at linkage (With the CA78K0R compiler, the area can be specified in the link directive file. With the CC-RL compiler, the area can be specified without allocating a section. With the LLVM compiler, the area can be specified in the linker script file). For the method of specifying the area in the link directive file, refer to the section "Defining the On-Chip RAM Area" in the release note.

2. 2. 3 Register bank

The Data Flash Library Type 04 uses the general registers, ES/CS register, SP, and PSW of the register bank selected by the user.

2. 2. 4 Stack and data buffer

The Data Flash Library Type 04 uses the sequencer to write to the data flash memory, but it uses the CPU for pre-setting and control. Therefore, to use the Data Flash Library Type 04, the stack specified by the user program is also required.

<R> Remark A link directive is used to allocate the stack and data buffer to user-specified addresses in the case of the CA78K0R compiler. A linker option is used to allocate the section in the case of the CC-RL compiler. A linker script file is used to allocate the stack and data buffer to user-specified addresses in the case of the LLVM compiler.

- Stack

In addition to the stack used by the user program, the stack space required for flash functions must be reserved in advance, and they must be allocated so that the RAM used by the user will not be destroyed in stack processing during the Data Flash Library Type 04 operation. The available range for stack specification is the internal RAM area excluding the self-RAM area and addresses FFE20H to FFEFFH.

- Data buffer

The uses of the data buffer are as follows.

- Area in which data to be written is located during writing
- Area in which data to be obtained is located during reading

The available range for the start address of the data buffer is the internal RAM area excluding the self-RAM area and RAM addresses FFE20H to FFEFFH, as in the stack.

2. 2. 5 Data flash library

Not all the data flash library functions are linked. Only the data flash library functions to be used are linked^{Note}.

- Memory allocation of the Data Flash Library Type 04

Segments are assigned to the functions and variables used in the Data Flash Library Type 04. Areas used in the Data Flash Library Type 04 can be specified to the specific locations.

Note For the assembly language, linking can be done only for the data flash library functions to be used by deleting unnecessary functions from the include file.

2. 2. 6 Program area

This is the area in which the Data Flash Library Type 04 and the user program using the Data Flash Library Type 04 are allocated.

In the Data Flash Library Type 04 for the RL78 microcontroller, the user program can be operated during rewriting of the data flash memory because the data flash memory is rewritten by using the sequencer (background operation).

2. 3 Cautions on Programming Environment

- (1) Do not execute the flash self-programming library, EEPROM emulation library, or data flash library other than Type 04 during the execution of the Data Flash Library Type 04. When using the flash self-programming library, EEPROM emulation library, or data flash library other than Type 04, be sure to execute PFDL_Close to close the data flash library.
- (2) Do not execute the STOP or HALT instruction during the execution of the Data Flash Library Type 04. If the STOP or HALT instruction needs to be executed, be sure to execute the PFDL_Close function to close the data flash library.
- (3) The watchdog timer does not stop during the execution of the Data Flash Library Type 04.
- (4) The data flash memory cannot be read during data flash memory operation by the Data Flash Library Type 04.
- (5) Do not allocate the arguments (data buffer) or stack used in the data flash library function to an address over 0xFFE20 (0xFE20).
- (6) When using the data transfer controller (DTC) during the execution of the Data Flash Library Type 04, do not allocate the RAM area used by the DTC to the self-RAM or an address over 0xFFE20 (0xFE20).
- (7) Do not use the RAM area (including self-RAM) used by the Data Flash Library Type 04 until data flash library is completed.
- (8) Do not execute a data flash library function within interrupt processing because the Data Flash Library Type 04 does not support multiple executions of data flash library functions.
- (9) When executing the Data Flash Library Type 04 on the operating system, do not execute data flash library functions from multiple tasks because the Data Flash Library Type 04 does not support multiple executions of data flash library functions.
- (10) Before starting the Data Flash Library Type 04, the high-speed on-chip oscillator needs to be started because it is used when the hardware in the RL78 microcontroller rewrites the contents of flash memory.

Data Flash Library Type 04

(11) Note the following regarding the operating frequency of the CPU and the operating frequency value set with the initialization function (PFDL_Open).

- When a frequency below 4 MHz^{Note1} is used as the operating frequency of the CPU, 1 MHz, 2 MHz, or 3 MHz can be used (a frequency such as 1.5 MHz that is not an integer value cannot be used). Also, set an integer value such as 1, 2, or 3 as the operating frequency value set with the initialization function.
- When 4 MHz^{Note1} or a higher frequency is used as the operating frequency of the CPU, a frequency with decimal places can be used. However, set a rounded up integer value as the operating frequency with the initialization function (PFDL_Open).
(Example: For 4.5 MHz, set "5" with the initialization function.)
- The operating frequency value of the CPU set with the initialization function (PFDL_Open) is not the operating frequency of the high-speed on-chip oscillator but the operating frequency used for execution of the user program. When the high-speed on-chip oscillator is to be used as the clock for execution of the user program, enter the operating frequency at which the high-speed on-chip oscillator is to run.

Note1 For the range of the operating frequency of the CPU, see the target RL78 microcontroller user's manual.

(12) The data flash control register (DFLCTL) should not be operated during the execution of the Data Flash Library Type 04. In addition, when the Data Flash Library Type 04 is ended, the DFLCTL is set to access inhibit state by the PFDL_Close function.

If accessing the data flash memory is required even after the Data Flash Library Type 04 is ended, confirm the completion of the PFDL_Close function, set the DFLCTL to the access permit state, and perform the setup process ^{Note2}.

Note2 For the method of the setup, see the target RL78 microcontroller user's manual.

(13) Initialize the arguments (RAM) that are used by the data flash library function. When they are not initialized, a RAM parity error is detected and the RL78 microcontroller might be reset.

For a RAM parity error, refer to the user's manual of the target RL78 microcontroller.

(14) Writing to the data flash memory can be performed only to an area in the blank state or the area that has been erased. It is impossible to rewrite (overwrite) to an area that has been written unless it has been erased. When rewriting is performed without erasing data, the data flash memory might be damaged.

(15) The Data Flash Library Type 04 does not perform error checking of the parameters set in the arguments of data flash library functions. Therefore, make sure to set a correct value to the parameter after checking the specifications of the target RL78 microcontroller. If parameter checking is required to set a correct value, perform it in the user program.

(16) Interrupts are inhibited for the R5F10266 product while the Data Flash Library Type 04 is in use.

Data Flash Library Type 04

(17) The segment (PFDL_COD) of the Data Flash Library for the CC-RL compiler for the RL78 family cannot be allocated to extend across the 64 Kbytes boundary. Be sure to allocate segments so that they do not extend across the 64 Kbytes boundary.

(18) When using an assembler of the CC-RL compiler from Renesas Electronics, the hexadecimal prefix representation (0x..) cannot be mixed together with the suffix representation (..H). Specify the representation method by editing the symbol definition in pfdl.inc to match the user environment.

pfdl.inc

```
__PFDL_INC_BASE_NUMBER_SUFFIX.SET 1
```

When symbol "__PFDL_INC_BASE_NUMBER_SUFFIX" is not defined (initial state), the prefix representation will be selected.

pfdl.inc

```
__PFDL_INC_BASE_NUMBER_SUFFIX.SET 1
```

When symbol "__PFDL_INC_BASE_NUMBER_SUFFIX" is defined, the suffix representation will be selected.

CHAPTER 3 DATA FLASH LIBRARY FUNCTION

This chapter describes the details of the data flash library functions.

3. 1 Type of Data Flash Library Functions

The Data Flash Library Type 04 consists of the following flash functions.

Table 3-1. List of Data Flash Library Functions

Function Name	Description
PFDL_Open	Initialization and starting of the RAM used for the Data Flash Library Type 04
PFDL_Close	Ending of the Data Flash Library Type 04
PFDL_Execute	Execution of control of the data flash memory
PFDL_Handler	Checking of the control state of the data flash memory and setting of continuous execution (status check processing)
PFDL_GetVersionString	Acquisition of the version information of the Data Flash Library Type 04

<R> 3. 2 Segment (Section) of Data Flash Library Functions

The entity of a data flash library function must be allocated to the specified area.

The entity is used as a segment when memory is allocated in the CA78K0R compiler and as a section in the CC-RL compiler and the LLVM compiler.

The segment (section) is configured as follows.

- PFDL_COD: Segment (Section) of the data flash library function.

This can be allocated to the ROM or RAM.

When using the data flash library for the CC-RL compiler and the LLVM compiler, read "segment" as "section" in the following descriptions.

3.3 Commands

The details of operation of the Data Flash Library Type 04 for the data flash memory can be specified with a command in the argument of the PFDL_Execute function. The commands specified in the PFDL_Execute function are shown below. For details on the execution method, refer to the section on the PFDL_Execute function.

Table 3-2. List of Commands Specified in PFDL_Execute Function

Definition	Value	Command Name
PFDL_CMD_READ_BYTES	0x00	Read command
PFDL_CMD_BLANKCHECK_BYTES	0x08	Blank check command
PFDL_CMD_ERASE_BLOCK	0x03	Erase command
PFDL_CMD_WRITE_BYTES	0x04	Write command
PFDL_CMD_IVERIFY_BYTES	0x06	Internal verification command

3.4 BGO (Background Operation)

The data flash library functions can be divided into functions that do not use the sequencer and functions that use the sequencer^{Note}. For the functions that use the sequencer^{Note}, BGO (background operation) can be performed.

The following shows examples of operation of the Data Flash Library Type 04 during BGO and the presence of sequencer control for each function.

Note Not during the execution of the PFDL_CMD_READ_BYTES command.

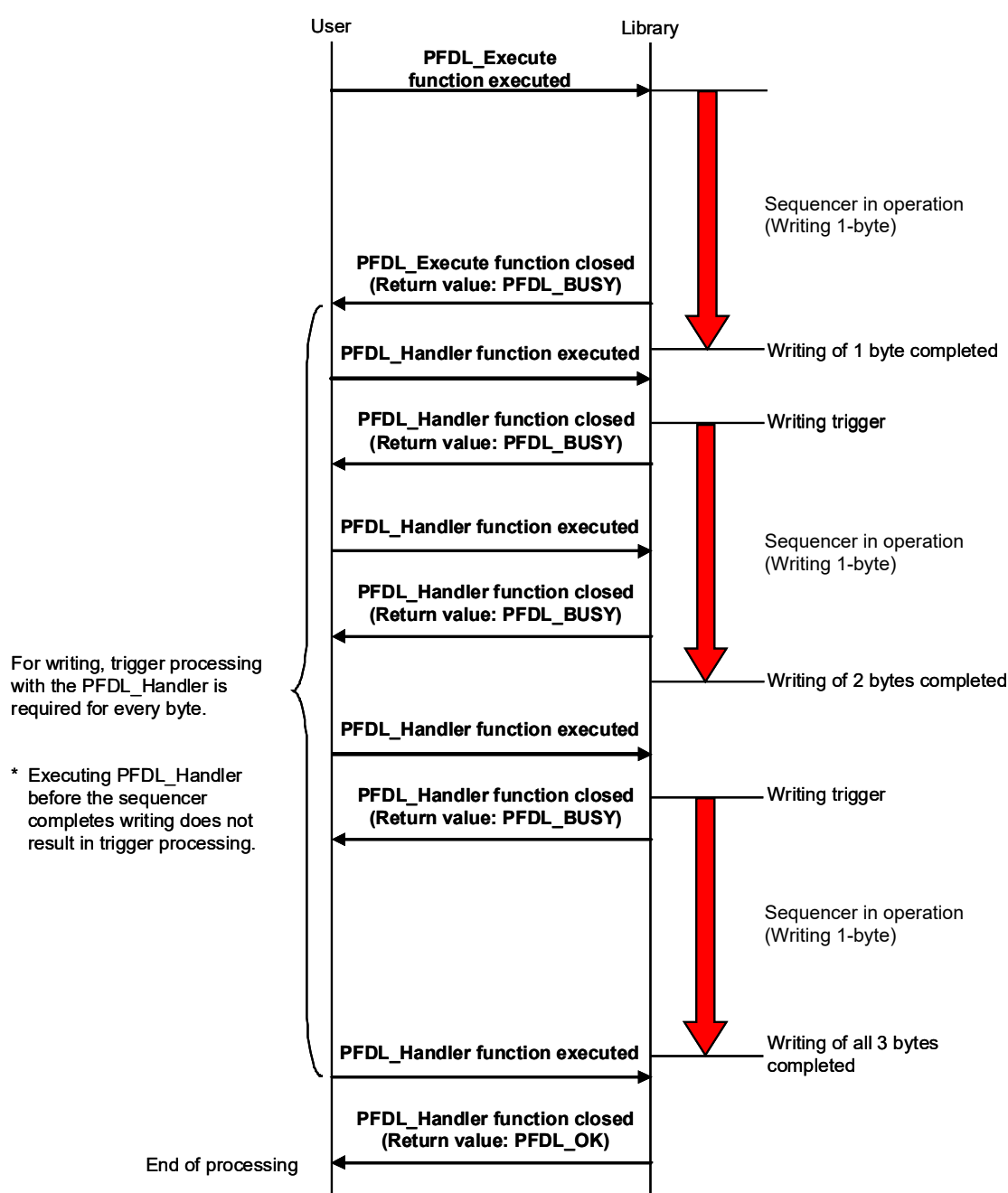


Figure 3-1. BGO Operation Example 1 (Write: Writing 3 Bytes)

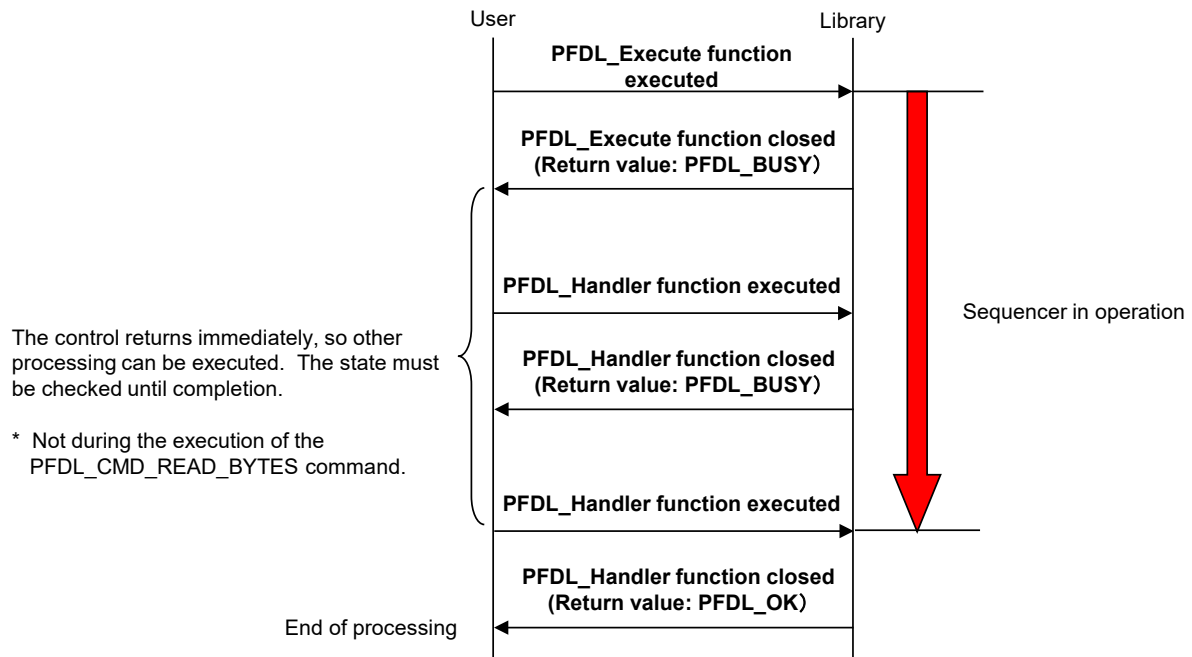


Figure 3-2. BGO Operation Example 2 (Erase, Iverify, BlankCheck)

Table 3-3. List of Interrupt Reception and BGO of Data Flash Library Functions

Function Name	Sequencer Control/BGO Function	Interrupt Reception
PFDL_Open	No	Allowed
PFDL_Close		
PFDL_Execute	Yes ^{Note}	
PFDL_Handler		
PFDL_GetVersionString	No	

Note Not during the execution of the PFDL_CMD_READ_BYTES command.

3. 5 List of Data Types, Return Values, and Return Types

The data types are as follows.

Table 3-4. List of Data Types

Definition	Data Type	Description
pfdl_u08	unsigned char	1-byte (8-bit) unsigned integer
pfdl_u16	unsigned int	2-byte (16-bit) unsigned integer
pfdl_u32	unsigned long int	4-byte (32-bit) unsigned integer

The meaning of each return value is as follows.

Table 3-5. List of Return Value Definitions (pfdl_status_t)

Definition	Return Value	Description
PFDL_OK	0x00	Normal completion
PFDL_ERR_ERASE	0x1A	Erase error - Erasure of the target area failed.
PFDL_ERR_MARGIN	0x1B	Blank check error or internal verification error - The target area is not in the blank state (not writable). - An error occurred during internal verification processing of the target area.
PFDL_ERR_WRITE	0x1C	Writing error - Writing to the target area failed.
PFDL_IDLE	0x30	Idle state - No command is executed in the PFDL_Execute function.
PFDL_BUSY	0xFF	Execution start of the PFDL_Execute function command, or in execution - The command specified in the PFDL_Execute function is in execution.
Other than above	Other than above	Other error - An abnormal return value. Check the specified command or resource allocation again.

<R> The general register used to pass a return value differs between the RENESAS CA78K0R, the RENESAS CC-RL and the LLVM compilers.

The return value and the general register used in each compiler are as follows.

Table 3-6. List of Return Values Used in Each Compiler

Development tool	Return Value	
	C Language	Assembly Language
RENESAS CA78K0R compiler	pfdl_status_t	C(General-purpose register)
RENESAS CC-RL compiler	pfdl_status_t	A(General-purpose register)
LLVM compiler	pfdl_status_t	A(General-purpose register)

<R>

3. 6 Description of Data Flash Library Functions

The flash functions are described in the following format.

Data flash library function name

[Overview]

Describes the function overview of this function.

[Format]

<C language>

Describes the format to call this function from a user program written in the C language.

<Assembler>

Describes the format to call this function from a user program written in the assembly language.

[Presetting]

Describes the presetting of this function.

[Function]

Describes the function details and cautions of this function.

[Register State After Call]

Describes the register state after this function is called.

[Argument]

Describes the argument of this function.

[Return Value]

Describes the return values from this function.

PFDL_Open

[Overview]

Initialization and starting of the RAM used for the data flash library

[Format]

<C language>

RENESAS CA78K0R compiler

```
pfdl_status_t __far PFDL_Open( __near pfdl_descriptor_t* descriptor_pstr )
```

RENESAS CC-RL compiler

```
pfdl_status_t __far PFDL_Open( __near pfdl_descriptor_t* descriptor_pstr )
```

<R> LLVM compiler

```
pfdl_status_t __far PFDL_Open( __near pfdl_descriptor_t* descriptor_pstr )
                                __attribute__((section ("PFDL_COD")))
```

<Assembler>

```
CALL !PFDL_Open or CALL !!PFDL_Open
```

Remark Call with "!" when the data flash library is allocated at 00000H to 0FFFFH, or call with "!!" otherwise.

[Presetting]

- The flash self-programming library, program and data flash library to operate the data flash memory, and EEPROM emulation library are not executed or have been ended.
- The high-speed on-chip oscillator is running.

[Function]

- Sets the data flash control register (DFLCTL) to the state where accessing the data flash memory is permitted (DFLEN = 1).
- Reserves, initializes and starts processing of the self-RAM used for the Data Flash Library Type 04. If a self-RAM^{Note 1} exists, do not use it until the Data Flash Library Type 04 is finished.
- Defines the flash memory programming mode^{Note 2} of the Data Flash Library Type 04 in the wide_voltage_mode_u08, a structure member of the argument pfdl_descriptor_t.
 - 0x00: Full speed mode
 - 0x01: Wide voltage mode
- Sets the operating frequency of the CPU in the fx_MHz_u08, a structure member of the argument pfdl_descriptor_t. The setting value is used for the calculation of timing data in the Data Flash Library Type 04^{Note 3}.

For the value of the operating frequency of the CPU (fx_MHz_u08), note the following.

- When a frequency below 4 MHz^{Note 4} is used as the operating frequency of the CPU, 1 MHz, 2 MHz, or 3 MHz can be used (a frequency such as 1.5 MHz that is not an integer value cannot be used). Also, set an integer value such as 1, 2, or 3 as the operating frequency value set with the initialization function.

Data Flash Library Type 04

- When 4 MHz or a higher frequency^{Note 4} is used as the operating frequency of the CPU, a frequency with decimal places can be used. However, set a rounded up integer value as the operating frequency set with the initialization function (PFDL_Open).

(Example: For 4.5 MHz, set "5" with the initialization function.)

- This is not the operating frequency of the high-speed on-chip oscillator.

- Notes
1. For more information on the self-RAM, refer to **2.2 Software Environment**.
 2. For details of the flash memory programming mode, refer to the user's manual of the target RL78 microcontroller.
 3. It is a required parameter for timing calculation in the flash self-programming library. This setting does not change the operating frequency of the CPU.
 4. For the range of the maximum operating frequency, refer to the user's manual of the target RL78 microcontroller.

Caution After executing this function, execute the PFDL_Close function. Do not set the data flash control register (DFLCTL) to the state where access to the data flash memory is inhibited (DFLEN = 0) until the Data Flash Library Type 04 ends.

[Register State After Call]

Development Tool	Return Value	Destructed Register
RENESAS CA78K0R compiler	C(General-purpose register)	AX
RENESAS CC-RL compiler	A(General-purpose register)	X,HL,C
LLVM compiler	A(General-purpose register)	X,HL,C

<R>

[Argument]

Definition of Argument

Argument	Description
<code>__near pfdl_descriptor_t* descriptor_pstr</code>	Initial setting value of the Data Flash Library Type 04 (The flash memory programming mode, CPU frequency)

Definition of `__near pfdl_descriptor_t`

Development Tool	C Language (Structure Definition)	Assembly Language (Example of definition)
RENESAS CA78K0R compiler	<pre>typedef struct { pfdl_u08 fx_MHz_u08; pfdl_u08 wide_voltage_mode_u08; } pfdl_descriptor_t;</pre>	<pre>_descriptor_pstr: _fx_MHz_u08 : DS 1 _wide_voltage_mode_u08 : DS 1</pre>
RENESAS CC-RL compiler	<pre>typedef struct { pfdl_u08 fx_MHz_u08; pfdl_u08 wide_voltage_mode_u08; } pfdl_descriptor_t;</pre>	<pre>_descriptor_pstr: _fx_MHz_u08 : .DS 1 _wide_voltage_mode_u08 : .DS 1</pre>
LLVM compiler	<pre>typedef struct { pfdl_u08 fx_MHz_u08; pfdl_u08 wide_voltage_mode_u08; } pfdl_descriptor_t;</pre>	<pre>_descriptor_pstr: _fx_MHz_u08 : .skip 1 _wide_voltage_mode_u08 : .skip 1</pre>

<R>

Contents of __near pfdl_descriptor_t

Structure Member	Description
fx_MHz_u08	CPU frequency during the execution of the Data Flash Library Type 04
wide_voltage_mode_u08	Setting of the flash memory programming mode

Contents of Argument Settings

Development Tool	Argument Type/Register	
	C Language	Assembly Language
RENESAS CA78K0R compiler	__near pfdl_descriptor_t* descriptor_pstr	AX (0 to 15) : The start address of the variable (16 bits)
RENESAS CC-RL compiler	__near pfdl_descriptor_t* descriptor_pstr	AX (0 to 15): The start address of the variable (16 bits)
LLVM compiler	__near pfdl_descriptor_t* descriptor_pstr	AX (0 to 15): The start address of the variable (16 bits)

<R>

[Return Value]

State	Description
0x00(PFDL_OK)	Normal completion - Initial setting is complete (there is no parameter other than normal completion)

PFDL_Close

[Overview]

Ending of the data flash library

[Format]

<C language>

RENESAS CA78K0R compiler

```
void __far PFDL_Close( void )
```

RENESAS CC-RL compiler

```
void __far PFDL_Close( void )
```

<R> LLVM compiler

```
void __far PFDL_Close( void ) __attribute__((section ("PFDL_COD")))
```

<Assembler>

```
CALL !PFDL_Close or CALL !!PFDL_Close
```

Remark Call with "!" when the data flash library is allocated at 00000H to 0FFFFH, or call with "!!" otherwise.

[Presetting]

Before the execution of this function, the PFDL_Open function must be completed normally.

[Function]

- Sets the data flash control register (DFLCTL) to the state where access to the data flash memory is inhibited (DFLEN = 0).

If accessing the data flash memory is required even after the Data Flash Library Type 04 is ended, confirm the completion of the PFDL_Close function, set the DFLCTL to the access permit state, and perform the setup process ^{Note}.

- Ends operation of the Data Flash Library Type 04.

Note For the method of the setup, see the target RL78 microcontroller user's manual.

[Register State After Call]

Development Tool	Return Value	Destructed Register
RENESAS CA78K0R compiler	-	-
RENESAS CC-RL compiler	-	C
LLVM compiler	-	C

<R>

[Argument]

None

[Return Value]

None

PFDL_Execute

[Overview]

Execution of control of the data flash memory

[Format]

<C language>

RENESAS CA78K0R compiler

```
pfdl_status_t __far PFDL_Execute(__near pfdl_request_t* request_pstr)
```

RENESAS CC-RL compiler

```
pfdl_status_t __far PFDL_Execute(__near pfdl_request_t* request_pstr)
```

<R> LLVM compiler

```
pfdl_status_t __far PFDL_Execute(__near pfdl_request_t* request_pstr)
                                __attribute__((section ("PFDL_COD")))
```

<Assembler>

```
CALL !PFDL_Execute or CALL !!PFDL_Execute
```

Remark Call with "!" when the data flash library is allocated at 00000H to 0FFFFH, or call with "!!" otherwise.

[Presetting]

Before the execution of this function, the PFDL_Open function must be completed normally.

[Function]

Executes the control of the data flash memory according to the specified command.

[Register State After Call]

Development Tool	Return Value	Destructed Register
RENESAS CA78K0R compiler	C(General-purpose register)	AX
RENESAS CC-RL compiler	A(General-purpose register)	X, BC, DE, HL
<R> LLVM compiler	A(General-purpose register)	X, BC, DE, HL

[Argument]

Definition of Argument

Argument	Description
__near pfdl_request_t* request_pstr	Specify the details of control of the data flash memory (command and setting value).

Note Initialize the variable area by inputting a value such as "0" before using as an argument of this function for a parameter for which a value is not necessarily set. When a variable including an area that has not been initialized is used, a RAM parity error is detected and the RL78 microcontroller might be reset.
For a RAM parity error, refer to the user's manual of the target RL78 microcontroller.

Definition of __near pfdl_request_t

<R>

Development Tool	C Language (Structure Definition)	Assembly Language (Example of Definition)
RENESAS CA78K0R compiler	typedef struct { pfdl_u16 index_u16; __near pfdl_u08* data_pu08; pfdl_u16 bytecount_u16; pfdl_command_t command_enu; }pfdl_request_t	_request_pstr: _index_u16 : DS2 _data_pu08 : DS2 _bytecount_u16 : DS2 _command_enu : DS1
RENESAS CC-RL compiler	typedef struct { pfdl_u16 index_u16; __near pfdl_u08* data_pu08; pfdl_u16 bytecount_u16; pfdl_command_t command_enu; }pfdl_request_t	_request_pstr: _index_u16 : .DS2 _data_pu08 : .DS2 _bytecount_u16 : .DS2 _command_enu : .DS1
LLVM compiler	typedef struct { pfdl_u16 index_u16; __near pfdl_u08* data_pu08; pfdl_u16 bytecount_u16; pfdl_command_t command_enu; }pfdl_request_t	_request_pstr: _index_u16 : .skip 2 _data_pu08 : .skip 2 _bytecount_u16 : .skip 2 _command_enu : .skip 1

Contents of __near pfdl_request_t

Structure Member	Description
pfdl_u16 index_u16	Start address of the target area or block number ^{Note1} - Erasure: Block number ^{Note1} - Other than erasure: Start address ^{Note1,3} of the target area
__near pfdl_u08* data_pu08	Pointer to the data buffer for acquisition of data to be written or read ^{Note1,2} Not used for processing other than writing/reading
pfdl_u16 bytecount_u16	Execution range of the command (byte specification) ^{Note1,2} - Erasure: No specification is required. - Other than erasure: Range from the specified start address ^{Note1} to the target area
pfdl_command_t command_enu	Command to execute

Notes 1 Initialize the variable area by inputting a value such as "0" before using as an argument of this function for a parameter for which a value is not necessarily set. When a variable including an area that has not been initialized is used, a RAM parity error is detected and the RL78 microcontroller might be reset. For a RAM parity error, refer to the user's manual of the target RL78 microcontroller...

- Specify it only for commands requiring the target parameter. Provide the data buffer size for the number of bytes of the data to be written or read.
- The specified address is the relative address that starts from block 0 of data flash memory (block 0 is assumed as address 0).

Contents of Argument Settings

<R>

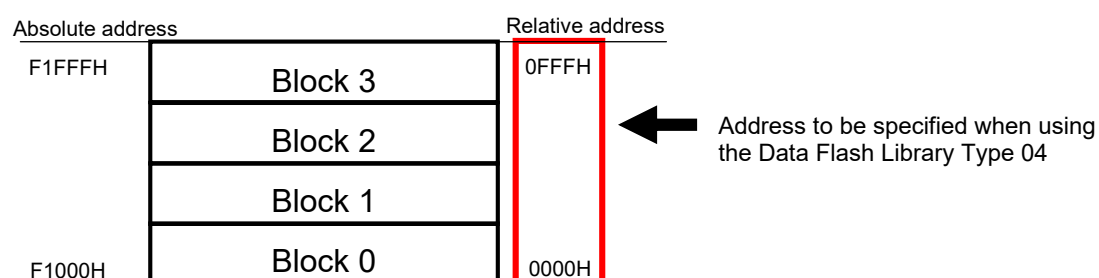
Development Tool	Argument Type/Register	
	C Language	Assembly Language
RENESAS CA78K0R compiler	__near pfdl_request_t* request_pstr	AX (0 to 15) The start address of the variable (16 bits)
RENESAS CC-RL compiler	__near pfdl_request_t* request_pstr	AX (0 to 15) The start address of the variable (16 bits)
LLVM compiler	__near pfdl_request_t* request_pstr	AX (0 to 15) The start address of the variable (16 bits)

List of Execution Commands (pfdl_command_t)

Command	Value	Description
PFDL_CMD_READ_BYTES	0x00	Reads the data of the read size from the specified start address^{Note2} of the data flash memory to the read data input buffer. Since the reading processing is not the background operation (BGO), all processing is executed in the PFDL_Execute function and the PFDL_Handler function does not need to be executed. *The following arguments must be set for execution. •pfdl_request_t.index_u16: Reading start address^{Note2} •pfdl_request_t.bytecount_u16: Read size^{Note1} •pfdl_request_t.data_pu08: Address of the read data input buffer
PFDL_CMD_BLANKCHECK_BYTES	0x08	Confirms that the execution range area is the erased level (writable area) by referring to the specified start address^{Note2} of the data flash memory. (Erased level cannot be confirmed by reading data.) In the case of an error, writing to the target area cannot be performed. When writing to an area where an error has occurred, the erasure command (PFDL_CMD_ERASE_BLOCK) must be executed. *The following arguments must be set for execution. •pfdl_request_t.index_u16: Start address^{Note2} •pfdl_request_t.bytecount_u16: Execution range from the start address^{Note1}
PFDL_CMD_ERASE_BLOCK	0x03	Performs erasure for the block of the specified number in the data flash memory. In the case of an error, writing to the target block cannot be performed. When writing to a block where an error has occurred, re-execute this command and normally terminate the execution. *The following argument must be set for execution. •pfdl_request_t.index_u16: Block number
PFDL_CMD_WRITE_BYTES	0x04	Writes the data input in the write data input buffer to the data flash memory from the specified start address^{Note2} for the write size. Writing to the data flash memory can be performed only to an area in the blank state or an area where data has been erased. It is not possible to perform rewriting (overwriting) to an area where data has already been written before the area is erased. Execute the internal verification command (PFDL_CMD_IVERIFY_BYTES) for an area to which data has been written to confirm the state of the data flash memory. *The following arguments must be set for execution. •pfdl_request_t.index_u16: Write start address^{Note2} •pfdl_request_t.bytecount_u16: Write size^{Note1} •pfdl_request_t.data_pu0: Address of the write data input buffer
PFDL_CMD_IVERIFY_BYTES	0x06	Performs internal verification from the specified start address^{Note2} of the data flash memory for the area in the execution range. This internal verification is a process to check if the signal level of the flash memory cells in the specified range is appropriate. When an error occurs, the written data is not guaranteed. When performing rewriting to the target area, execute the erasure command (PFDL_CMD_ERASE_BLOCK). *The following arguments must be set for execution. •pfdl_request_t.index_u16: Start address^{Note2} •pfdl_request_t.bytecount_u16: Execution range from the start address^{Note1}

Data Flash Library Type 04

- Notes
- 1 It cannot be specified across blocks. Specify it within one block.
 - 2 The specified address is the relative address that starts from block 0 of the data flash memory (block 0 is assumed as address 0) when writing and reading the memory. Note that the specified address is not an absolute address.



[Return Value]

State	Description
0x00(PFDL_OK)	Normal completion
0x1A(PFDL_ERR_ERASE)	Erasure error - An error occurred during erasure processing.
0x1B(PFDL_ERR_MARGIN)	Blank check error or internal verification error - The target area is not in the blank state (not a writable area). - An error occurred during internal verification processing of the target area.
0x1C(PFDL_ERR_WRITE)	Writing error - An error occurred during write processing.
0xFF(PFDL_BUSY)	Execution start of the specified command - The execution of the specified command has been started. (Check the execution state with the PFDL_Handler function.)

PFDL_Handler

[Overview]

Checking of the control state of the data flash memory and setting of continuous execution (status check processing)

[Format]

<C language>

RENESAS CA78K0R compiler

```
pfdl_status_t __far PFDL_Handler( void )
```

RENESAS CC-RL compiler

```
pfdl_status_t __far PFDL_Handler( void )
```

<R> LLVM compiler

```
pfdl_status_t __far PFDL_Handler( void ) __attribute__((section ("PFDL_COD")))
```

<Assembler>

```
CALL !PFDL_Handler or CALL !!PFDL_Handler
```

Remark Call with "!" when the data flash library is allocated at 00000H to 0FFFFH, or call with "!!" otherwise.

[Presetting]

Before the execution of this function, the PFDL_Open function must be completed normally.

[Function]

Checks the control state of the command (other than the PFDL_CMD_READ_BYTES command) specified in the PFDL_Execute function executed immediately before this function and performs required settings for continuous execution.

[Register State After Call]

Development Tool	Return Value	Destructed Register
RENESAS CA78K0R compiler	C(General-purpose register)	-
RENESAS CC-RL compiler	A(General-purpose register)	C
LLVM compiler	A(General-purpose register)	C

<R>

[Argument]

None

[Return Value]

State	Description
0x00(PFDL_OK)	Normal completion
0x1A(PFDL_ERR_ERASE)	Erase error - An error occurred during erasure processing.
0x1B(PFDL_ERR_MARGIN)	Blank check error or internal verification error - The target area is not in the blank state (not a writable area). - An error occurred during internal verification processing of the target area.
0x1C(PFDL_ERR_WRITE)	Writing error - An error occurred during write processing.
0x30(PFDL_IDLE)	Idle state - No command is executed in the PFDL_Execute function.
0xFF(PFDL_BUSY)	Command in execution - The command specified in the PFDL_Execute function is being executed.

PFDL_GetVersionString

[Overview]

Acquisition of the version information of the Data Flash Library Type 04

[Format]

<C language>

RENESAS CA78K0R compiler

```
__far pfdl_u08* __far PFDL_GetVersionString( void )
```

RENESAS CC-RL compiler

```
__far pfdl_u08* __far PFDL_GetVersionString( void )
```

<R> LLVM compiler

```
__far pfdl_u08* __far PFDL_GetVersionString( void )  
  
__attribute__((section ("PFDL_COD")))
```

<Assembler>

```
CALL !PFDL_GetVersionString or CALL !!PFDL_GetVersionString
```

Remark Call with "!" when the data flash library is allocated at 00000H to 0FFFFH, or call with "!!" otherwise.

[Presetting]

None

[Function]

Obtains the version information of the Data Flash Library Type 04.

[Register State After Call]

Development Tool	Return Value	Destructed Register
RENESAS CA78K0R compiler	BC (0 to 15), DE (16 to 31)	-
RENESAS CC-RL compiler	DE(0-15), A(16-23)	-
<R> LLVM compiler	DE(0-15), A(16-23)	-

[Argument]

None

[Return Value]

Data Type	Description
<R> __far pfdl_u08*	The version information storage start address of the Data Flash Library Type 04. (far area) The version information of the flash self-programming library consists of ASCII characters. Example: Data Flash Library Type 04 "DRL78T04LyyyzGVxxx" Version information: Example: V105 -> V1.05 Compiler information(5 or 6 characters): CA78K0R [ex:RyyyG] CC-RL and LLVM [ex:LyyyzG] Type No.(3 characters): : T04 -> Type 04 Supported device(4 characters) : RL78 Target library(1 character) : FDL

APPENDIX A REVISION HISTORY

A. 1 Major Revisions in This Edition

Page	Description	Classification
Throughout the document		
-	Added information on the data flash library for the LLVM compiler.	(b)
-	Moved the title of the figure number from the top of the figure to the bottom.	(c)
Chapter 2 Programming Environment		
p.18	Added explanation about the LLVM compiler	(c)
p.18, p.20	Added software resources for the LLVM compiler in Table 2-7 and Table 2-8.	(c)
p.18, p.22-P22	Added stack information needed when using the LLVM compiler.	(c)
p.23	Added explanation for allocating the self-RAM area when using the LLVM compiler.	(c)
p.23	Added explanation for setting the stack when using the LLVM compiler.	(c)
Chapter 3 Data Flash Library Function		
p.28	Added explanation about the LLVM compiler	(c)
p.32 - p.45	Added settings for the LLVM compiler return values, C language format and argument definitions for each function.	(c)

Remark "Classification" in the above table classifies revisions as follows.

- (a): Error correction, (b): Addition/change of specifications, (c): Addition/change of description or note,
- (d): Addition/change of package, part number, or management division,
- (e): Addition/change of related documents

A. 2 Revision History of Preceding Editions

Here is the revision history of the preceding editions. Chapter indicates the chapter of each edition.

Rev.	Description	Chapter
Rev.1.06	The English translation was reviewed and corrected.	Throughout the document
	The user's manual of the flash self-programming library for CC-RL was integrated into this manual.	
	A statement regarding reference to the RL78 Family Self RAM list of the target MCU was added (see HOW TO USE THIS MANUAL).	
	The ZIP file name was changed to the installer name.	Cover
	A supplementary explanation of the note on areas to which writing has already proceeded was added.	Chapter 1 Overview
	A description regarding the supported compilers was added.	Chapter 2 Programming Environment
	In Table 2-7 and 2-8, the software resources for the CC-RL compiler were added.	
	In Table 2-8, the stack sizes for the CC-RL compiler were added.	
	The methods for allocating the self-RAM area and specifying desired addresses for the CC-RL compiler were added.	
	The methods for allocating the stack for the CC-RL compiler were added.	
	A description regarding the start of the high-speed on-chip oscillator was added.	
	The description that each segment must not extend across a 64 Kbytes boundary was added.	
	The method for representing hexadecimal numbers in the assembler in the RENESAS CC-RL compiler package was added.	
	The heading of section 3.2 was changed ("Section" was added).	Chapter 3 Data Flash Library Function
	The description regarding allocation to specified areas was reviewed and corrected.	
	Statements of the return values, formats of the C language call, and definitions and contents of the arguments of each of the library functions were added and changed.	

Rev.	Description	Chapter
Rev.1.05	The English translation was reviewed and corrected.	Throughout the document
	The target device descriptions were deleted.	
	References to the list of the target MCUs were added.	
	The term "voltage mode" was changed to "flash memory programming mode" for consistency of terminology.	
	Various types of operating frequency described in the former version were unified to the CPU operating frequency.	
	A description of the case when flash functions are executed in the RAM was added.	Chapter 2 Programming Environment
	The title of Table 2-2 was corrected.	
	A description that the reading processing is excluded from the conditions of status check was added.	
	The description in (3) Total processing time was reviewed and corrected.	
	The titles of Tables 2-5 and 2-6 were corrected.	
	In Tables 2-5 and 2-6, the title of the Reference column was changed to "Typical" and its contents (formulas) were changed.	
	The resources used to run the data flash library were corrected.	
	In Table 2-7, the self-RAM size was changed.	
	In Table 2-7, the description of the self-RAM area was changed.	
	Note 1 on Table 2-7 was changed to a description of the inquiry about device specifications.	
	In Figure 2-12, the remaining user stack size was corrected.	
	The description of the self-RAM was reviewed and corrected.	
	In Table 3-6, the name of the return type in the C Language column was corrected.	Chapter 3 Data Flash Library Function
	The names of the members of the pfdl_descriptor_t structure were corrected.	
	For PFDL_CMD_READ_BYTES in the List of Execution Commands (pfdl_command_t), a description that the PFDL_Handler function does not need to be executed was added.	
	A description that execution of the PFDL_Handler function is necessary for the commands other than PFDL_CMD_READ_BYTES was added.	

Rev.	Description	Chapter
Rev.1.04	The document on the data flash library, which was classified as the application note (old version of R01AN0608), was changed to the user's manual.	Throughout the document
	The corresponding ZIP file and release version were added to the cover page	
	RL78/L13 were added to the supported devices	
	The name of the flash data library was changed to the data flash library.	
	Contents of the processing time and software resources were moved from the usage note to this document. Accordingly, the reference destination described in this document was also changed	
	The notation of high-speed OCO was deleted to unify the notation of high-speed on-chip oscillator	
	The description of the operating frequency was unified to the operating frequency of CPU since individual descriptions had different notations.	
	Errors in the format of the assembly language for executing functions were modified.	
	Supplemental information was added to the terms of the blank state and blank check.	
	Controls to the data flash control register (DFLCTL) were added.	Chapter 1 Overview
	Note on writing was added.	
	Note (description) on internal verification was added.	
	Note describing that an interrupt becomes inhibited when the R5F10266 product is in use was added.	Chapter 2 Programming Environment
	Description on the initial setting was added.	
	Description on the data flash control register (DFLCTL) was added.	
	Note on the address specified by the data flash library was added.	
	Items on the processing time was added (description on the processing time was moved from the usage note to this document).	
	The reference (referred to min in older versions) time of Erase and BlankCheck was deleted.	
	Items of RL78/L13 were added to the resources	
	Items on the resource were added (description of the resource was moved from the usage note to this document).	
	Note on the data buffer was added	
	The contents of resources when the R5F10266 product is in use were added.	
	Note on the frequency of the high-speed on-chip oscillator was added.	
	Note on the data flash control register (DFLCTL) was added.	
	Note on the RAM parity error was added.	
	Note for writing was added.	
	Note describing that an interrupt becomes inhibited when the R5F10266 product is in use was added.	
	Note on the data flash control register (DFLCTL) was added.	

Rev.	Description	Chapter
Rev.1.04	Description on the data flash control register (DFLCTL) was added.	Chapter 3 Data Flash Library Function
	Setting value of the wide voltage mode was changed from "other than 00H" to "01H" (values from 02H to FFH can normally be set but the description was changed since the defined value in the specification was 01H).	
	Note on the frequency of the high-speed on-chip oscillator was added.	
	Note on the data flash control register (DFLCTL) was added.	
	Definition of the structure and the table for setting the argument were added and modified.	
	Description on the data flash control register (DFLCTL) was added.	
	Note on the data flash control register (DFLCTL) was added.	
	Notes on the RAM parity error were added.	
	Table for the definition of the structure was added.	
	Table of the argument and register type was added.	
	Note on the address specified by the data flash library was added.	
	Descriptions on individual commands were added	
	Note for writing was added.	
	Note (description) on the internal verification was added.	
	Deleted the index.	

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Data Flash Library Type 04

